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MINIATURE PRECISION DETONATOR

SPACE ORDNANCE SYSTEMS, INC. 375 SANTA TRINITA AVENUE SUNNYVALE, CALIFORNIA 94086

JUNE 1974

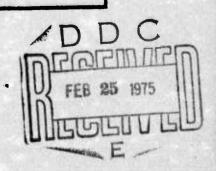
FINAL REPORT FOR PERIOD JULY 1973 - MAY 1974

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20. ABSTRACT (Continue on reverse side if necessary and identify by block number)

This report describes a two-pin miniature precision detonator (MPD) for use in space-limited safety and arming (S&A) devices providing multipoint initiation of missile warheads. The detonator is a fast-acting electric type not larger than the single-pin USAF Microdetonator, P/N 66A11302, but with less sensitivity (80 milliamperes versus the specified 10 milliamperes for the Microdetonator no-fire). The foremost purpose of the design is simultaneous initiation

ITEM 20. ABSTRACT (CONCLUDED)

of a number of detonators. This is best achieved by a very short firing time for the nominal unit. Two header designs were evolved: (1) platinum-tungsten alloy 479 wire bridge and (2) thin-film palladium bridge, vacuum deposited on a vacuum deposited chromium base. The two headers were used to make full-up detonators. Both headers and detonators were tested using a capacitive discharge firing unit (22-microfarad capacitor charged to 30 to 40 volts). Test units were fired by mercury relay. Firing times were 4 to 5 microseconds with \$\frac{1}{2}\$ in microsecond jitter for the wire bridge and 1 microsecond \$\frac{1}{2}\$0.5 microsecond for deposited bridge. The deposited bridge units were therefore preferable for use where simultaneity is important. Another finding was that dimple-ended aluminum cases are superior in gap transfers into PBXN-5 acceptor when compared to equivalent mass stainless steel cases, either dimpled or flat bottomed. Also, flat bottomed stainless steel cases perform better than dimpled cases. Test data on the two headers and the two miniature detonators made from them are included.

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SUMMARY

- The Deposited Bridge Miniature Precision Detonator (DBMPD) and the Wire Bridge Miniature Precision Detonator (WBMPD) will function in less than ten microseconds with less than one microsecond jitter. The minimum firing stimulus is the discharge of a 22-microfarad capacitor at approximately 40 volts through the MPD bridge.
- The MPD manufacturing procedure must be altered to eliminate the MPD functional problems. The changes are in the primer charge slurry blend and the soldering sealing technique.
- The no-fire current for WBMPD and DBMPD is approximately 0.10 ampere.
- The MPD output was not affected by the environmental tests (T&H and Shock). The leads of approximately 50% of the MPD rusted off during the T&H test. Detonators failed functionally after the tests but the failures were attributed to desensitization of the primer charge during manufacturing.
- The MPD will reliably initiate PBXN-5 at 30 Kpsi through 0.005-inch-thick (maximum) aluminum or stainless steel closure across a 0.075 inch (maximum) air gap.
- Three 0.022-inch-thick steel barriers are required to confine the MPD output.
- During the week of June 10, 1974, eleven flat-bottomed stainless steel cases were loaded with 17 milligrams HMX plus 24 milligrams, lead azide. These were fired with an electric match to determine the gap transfer characteristics into a PBXN-5 acceptor with a 5-mil aluminum closure. At 0.250 inch gap, 5/5 transfers occurred. At 0.500 inch, 4/6 transfers occurred. This contrasts to approximately 0.075 inch gap for reliable transfer with the dimpled stainless steel can.
- The techniques utilized in manufacture of the Deposited Bridge Miniature Precision Detonator headers are not adequate to insure consistent and reliable function and must be improved.

PREFACE

This report documents work performed by Space Ordnance Systems, Inc., 375 Santa Trinita Avenue, Sunnyvale, California 94086 under Contract No. F08635-73-C-0156 with the Air Force Armament Laboratory, Eglin Air Force Base, Florida. Mr. Richard B. Mabry, Jr. (DLJF) managed the program for the Armament Laboratory. This effort was conducted during the period from July 1973 to May 1974.

This report also documents a reliability evaluation of deposited bridge headers performed by J.J. Bart, E.A. Doyle and C. J. Salvo of Rome Air Development Center/RBRP.

This technical report has been reviewed and is approved for publication.

FOR THE COMMANDER

ENDRUCK J. SMITH. JR. CO. D. USAF

Chief, Fuzes and Munition Control Systems Division

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SECTION I

INTRODUCTION

A program was undertaken to determine the feasibility of designing and building a miniature detonator which will function in less than 10 microseconds, with less than one microsecond jitter. The detonator size was specified to be comparable to the USAF Microdetonator P/N 66All302 (SOS 06401) developed for Air Force WAAPM program, but with the following differences:

- Less sensitivity than the Microdetonator (80 milliamperes no-fire, compared to 10 milliamperes specified for the Microdetonator)
- Lead azide rather than lead styphnate used in the primer

Both alloy 479 platinum-tungsten wire bridges and thin-film, vacuum-deposited chromium-palladium bridges were investigated. To meet the less than 10 microsecond firing time requirement, capacitive discharge firing units were used. With 22 microfarad capacitor charged to 40 volts dc, fired by a mercury relay, firing times of 4-5 microseconds and 1.0 microsecond jitter were achieved with wire bridges. Deposited bridges fired in 1.0 microsecond and 0.5 microsecond jitter.

The new detonator was called the Miniature Precision Detonator (MPD).

This document describes the development program and the results of the development verification. The one exception to the test plan is that an additional 100 Wire Bridge MPDs were included in the test matrix.

SECTION II

OBJECTIVES

2.1 Firing Time

Capacitor discharge firing in less than 10 microseconds and with less than one microsecond jitter.

2.2 No-Fire Current

Establish no-fire current. The no-fire current is to be greater than 0.080 ampere.

2.3 Detonator Output

Characterize the detonator output by the following tests.

- 2.3.1 Dent Output Test. Test detonators into steel witness plate to compare dent outputs.
- 2.3.2 <u>Gap Test</u>. Determine the maximum air gap across which the detonator will initiate a PBX-N5 booster.
- 2.3.3 <u>Booster</u> (Variable Closure) Initiation Test. Determine the maximum booster closure (aluminum and stainless steel) thickness through which the detonator will initiate PBX-N5.
- 2.3.4 Barrier Test. Determine the barrier necessary to confine the detonator output for safety reasons.

2.4 Temperature and Humidity Test

Determine if detonators will resist degradation when exposed to the temperature and humidity environment.

2.5 Shock Test

Determine if detonators will withstand the 1500-g shock test without degradation.

SECTION III

MINIATURE PRECISION DETONATOR DESIGN

3.0 General

The Miniature Precision Detonator (MPD) design is shown in SOS Drawing 10314 (Appendix A). The electrical initiation characteristics and the detonator material are modified from the Microdetonator (SOS 06401) to effect a design meeting the requirements of the contract.

3.1 Configuration

The configuration of the MPD (SOS Drawing 10314) is essentially identical to that of Microdetonator (SOS Drawing 06401), Spec. 66All302, Rev. D, except for two lead pins rather than one pin, and a steel case rather than aluminum. The MPD diameter is 0.100 inch maximum. The lead-pin length is 0.23 inch. The two lead pins are electrically isolated from the case by a fused glass bead.

3.2 <u>Header Assembly</u>

The two types of header assemblies are shown in SOS Drawing 10362 and 10507 (Appendix A).

- 3.2.1 <u>Header</u>. The header configuration is shown in SOS Drawing $1035\overline{3}$ (Appendix A). A glass-to-metal header is employed in the design. The sleeve and the two lead pins are Kovar with gold plating. The insulating seal is glass. The lead pin is 0.012 ± 0.001 inch in diameter by 0.25 inch long.
- 3.2.2 <u>Bridge</u>. Detonators with two types of bridge construction were developed: (1) wire bridge, and (2) vapor-deposited bridge. The two types of bridge are discussed below.
- 3.2.2.1 <u>Wire Bridge</u>. Several types of bridgewires were welded onto headers, buttered with primer charge (lead azide) and fired. The tests were primarily directed towards obtaining the fast function time of less than 10 microseconds. The 479 alloy (platinum-tungsten) wire, 0.0004-inch diameter, met the requirement.

Initial tests were performed with one-pin headers, SOS 08543. The tests showed that, with a given stimulus, shortening the bridge element which, in turn, lowers the bridge resistance, shortened the function time. The lowest resistances ranged between 2.0 to 2.7 ohms.

With the two-pin header, SOS 10353 (Appendix A), the shorter bridge was not attained because the header pin-to-pin spacing was wider than the pin-to-sleeve spacing of the one-pin header. The bridge resistance ranged between 3.8 to 4.8 ohms. It was noted that welding the bridgewire with high energy seemed to result in a higher frequency of fast function time (2 to 3 microseconds) but not repeatably. Bridgewires were welded with minimum energy so as not to overly deform the wire at the weld spots.

3.2.2.2 <u>Vapor Deposited Bridge</u>. The bridge configuration is shown in SOS Drawing 10506 (Appendix A). The element itself is the same as the bridge designed for the one-pin Microdetonator header, SOS 08892. To vapor deposit a bridge on a header, the glass surface must be smooth and clean.

The header supplier was asked to polish the glass surface in an electric fusion furnace but the effort did not succeed. The entire glass bead melted, and the pins moved so that the header no longer met the dimensions specified in SOS Drawing 10353.

The one-pin headers of the Microdetonator were routinely polished in the furnace. In the one-pin configuration, the single axial pin could be maintained in position by a support which did not induce any stress relative to the shell. In the case of the two-pin models, there was no immediate solution to pin support without inducing some undesirable force moments causing the pins to move out of specification. The inability to polish the two-pin headers in the supplier's furnace was not anticipated.

It was decided to polish the headers in-house. Headers with large voids or cracks on the glass surface were segregated out beforehand. The area of glass shown in Figure B-8, Appendix B, was polished with a small acetylene-oxygen torch. Attempt was made to polish the whole surface, but the glass retracted downward, creating a void around each pin.

A polished glass surface on the header is essential to success in vapor deposition of a pin-to-pin bridge across the glass. A bridge carnot be deposited across or through a large void.

The in-house polishing with oxy-acetylene torch could also result in damaged headers if flame exposure were too concentrated or for too long a period. For assurance that headers were not damaged in polishing, the flame exposure was restricted to the area immediately between the two pins. Very few deposited bridge headers so prepared were lost because of open circuits from bad depositions. For example, in two runs of 396 headers only three headers were rejected. Thus, in 792 headers only six were defective in the deposition process.

The polished headers were cleaned in hot water, hot acetone, and hot alcohol to remove any soluble salts and oily substances. The headers were dried with dry nitrogen and stored in nitrogen atmosphere. The deposition fixtures (SOS 54799) were cleaned in acetone and alcohol and dried with dry nitrogen. No part was handled after cleaning without cotton gloves or clean tweezers. The headers were placed in the fixture (SOS 54799), Figure B-8, Appendix B.

The deposition work was done by Alphadyne, Inc., Sunnyvale, California. Three runs were made, and the results are given in Appendix B, Tables B-1, B-2 and B-3. The data show the location of the header in the fixture versus the bridge resistance. The deposition consists of approximately 200 Angstrom of chromium base with 4000, 4200, and 4800 Angstrom of paladium for Runs #1, #2, and #3, respectively. Deposition thickness was increased for successive uses of the mask to compensate for closure of the mask apertures by residual deposition. The step increases in thickness were determined by experience as required to maintain the bridge resistance.

In general, the bridge resistance decreased, going from top to bottom. This was due to the positioning of the vapor deposition fixture within the deposition chamber. The irregular resistances are mainly due to the headers not being up against the deposition mask because the header is stuck in the fixture hole or the header top is not perpendicular.

The vapor deposition is done at elevated temperature (150°C) and then brought down to room temperature. Normally, a poor bond will peel off in the cooling process. This means that the cooling process provides an automatic selection process to identify the poor bonds. Deposited bridges which survive the cooling stresses are probably satisfactory units.

Some of the headers in the first two runs had cracked glass. It was certain that it was not due to the polishing operation because the polished headers were 100% inspected for cracks and quality of polish. For Run #3, the headers were cleaned in 150°F water rather than boiling water (212°F). Some cracking occurred when the headers were boiled in water. After

positioning in the fixture, headers were 100% inspected. No cracks were noted. Before the bridge was deposited, both headers and fixture were heated in the deposition chamber to remove any moisture present on the headers.

For Run #3, the time to reach the temperature was lengthened from 8 minutes to 15 minutes to reduce thermal shock. Very few headers were lost due to cracked glass in Run #3. Headers for the test were selected from the three runs. The headers were selected for bridge resistance (2.5 to 4.5 ohms). All headers were visually inspected for proper bridge. Function tests showed that headers with bridge resistance above 5 ohms did not always initiate the primer charge.

One hundred vapor deposited bridge headers (SOS 10507) were shipped to AFATL, Eglin Air Force Base, Florida.

3.2.3 Primer Charge. Lead azide and silver azide were suggested for the primer charge in the AFATL specification. Lead azide (RD 1333) particle size was found to be much larger than the bridge, and therefore the explosive was milled. Colloidal lead azide was obtained from Naval Weapons Center, China Lake, California. The particle size of the milled lead azide and the colloidal lead azide were about the same.

Tests made with both types of lead azide showed no difference between the two. The lead azide is applied to the header in a slurry form. The slurry consists of lead azide, butyl acetate, and 1% Viton "A" binder. The buttered header is dried at 170°F for 30 minutes minimum. Milled lead azide was used on all test hardware.

One problem noted was that the slurry dried with a concave surface over the bridge area. This is depicted in Figure B-9A, Appendix B. This does not present a problem with the one-pin header assembly because the bridge is located underneath the crest area of the primer charge. A thin layer of primer charge over the bridge area may cause the bridge not to heat a critical mass and, hence, result in long function time. In the worst condition, the assembly may not function at all. Header assemblies for the test were inspected for thin primer charge over the bridge area and exposed bridge.

After the test assemblies were fabricated, an investigation was made to find a solution to the before-mentioned problem. Addition of isopropyl alcohol to the slurry mix was found to cure the problem. The addition of alcohol allowed the slurry to dry more slowly. The header assembly buttered with this slurry is depicted in Figure 3-9B.

3.3 Case Assembly

3.3.1 Case. The case configuration is shown in SOS Drawing 10352, Appendix A. The case material is stainless steel with the same dimple end as the Microdetonator case. The case is tin plated for solderability. The bottom thickness is 0.004 ± 0.001 inch. It would be desirable to have 0.002 to 0.003-inch-thick bottom so that the mass of the end plate (case bottom) will be nearly the same as the mass of the Microdetonator aluminum case bottom. Detonators fabricated with these cases will nearly have the same output. That is, when the detonators are functioned, the velocity of the end plates should be nearly the same. It turns out that the case bottom thickness is approximately 0.005 inch which is the same as the wall thickness. Stainless steel cannot be coined to a thinner thickness; therefore, the only way to thin the case bottom is by machining or lapping.

In the early stage of the program, a series of tests to obtain some data on how the case bottom thickness affects the detonator output were made. A smaller ID (0.081 inch) steel case was tested with the same amount of transfer and output charges as the Microdetonator. Prior to loading, the bottom of four cases was thinned to 0.005 inch and shaped to have the same dimple as the Microdetonator case. The loaded cases were tested into WAAPM HMX boosters at 0.150 inch air gap (test gap for Microdetonator). All transferred successfully. This test was repeated with five 0.007- and five 0.009-in htthick bottom cases. Each initiated its respective booster. The same test was repeated with the first cases (SOS 10353) shipped by the vendor to SOS for evaluation. In five tests, the case assemblies initiated their respective boosters.

The standard aluminum case Microdetonator is dimpled as experience showed would increase the output efficiency due to the "flying plate" principle. The first tests with stainless steel cases used a dimpled case similar to the aluminum cases except for wall thickness which was reduced from 8 mils to 5 mils to maintain approximate mass equivalency between the two cases. The same dimple radii were used.

The stainless steel dimpled cases were found to be inferior to aluminum in gap transfer tests. Stainless steel transferred at 0.075 inch, compared to as much as 1.0 inch for aluminum. The stainless steel case wall thickness was reduced to approximately 2 mils to bring the mass equivalence more closely to that of aluminum. Gap firing tests with the 2-mil dimpled stainless steel cases showed reliable transfer at approximately 0.100 inch, still much less than achieved by the equivalent aluminum cases.

The poor results with the dimpled cans suggested the use of normal fragmentation as the transfer mode and so flat-bottom cases were tried. A total of 14 flat-bottom units were assembled. Three of these were removed for dent output evaluation over several gaps. The purpose of these dent firings was to provide a gross evaluation of the fragmentation coverage and depth relative to several selected gap distances. (Dent depth firings are not good criteria for evaluating effectiveness of transfer but indicate only relative consistency of output between similar units.) The remaining 11 units were fired into PBXN-5 boosters with 5-mil aluminum closures, at gaps of 0.250 and 0.500 inch. The results were 5 out of 5 ruccessful transfers at 0.250 and 4 out of 6 successful at 0.500 inch. This showed that flat-bottomed stainless steel cases were superior to the dimpled ones.

It is recommended that stainless steel test configurations be standardized on flat-bottomed cases in all future tests.

- 3.3.2 Transfer Charge. The same transfer charge (lead azide) as in the Microdetonator was used in the test assembly. The amount was increased to compensate for the larger ID of the stainless steel case (SOS 10353). The charge was 23 ± 2 milligrams of lead azide consolidated at 15 Kpsi; reference column height was 0.060 inch.
- 3.3.3 Output Charge. The same output charge (HMX) as in the Microdetonator was used in the test assembly. The amount was increased to compensate for the larger ID of the case. The charge was 18 ± 2 milligrams of HMX consolidated at 15 Kpsi; reference column height was 0.100 inch.

3.4 Sealant

The header-to-case interface was sealed with Sn63 solder. A 0.027-inch-diameter solder sphere with Kester Paste Flux was positioned at the interface and soldered with an RF-induction heater. Microdetonators have been solder-sealed using the same method. The Microdetonator aluminum case was plated, and a 0.027-inch-diameter 50 Tin/50 Indium alloy solder sphere was used for its lower melting temperature.

SECTION IV

TESTS

The tests performed for the Miniature Precision Detonator (MPD) are outlined in the Test Plan. By mutual agreement, one hundred wire bridge MPD (SOS 10314-101) were added to the test matrix.

4.1 Leak Test

One hundred ten vapor deposited bridge MPD (SOS 10314-103) and 57 wire bridge MPD (SOS 10314-101) were subjected to the leak test. All MPD with leak rate greater than 1 X 10^{-6} cc/sec of helium were rejected. Remainder of wire bridge MPD were not solder-sealed.

4.2 Temperature and Humidity Test

Thirty-two wire bridge MPD and 32 vapor-deposited bridge MPD were subjected to the 28-day temperature and humidity test in accordance with MIL-STD-331, Test 105. The bridge resistances were measured and recorded before and after completion of the test.

4.3 Shock Test

Fifteen wire bridge MPD and 15 vapor-deposited bridge MPD were subjected to the 15,000 "g" shock test. In each test, 15 MPD were mounted in a carrier and launched with an air gun into a pine board laid on loose sand. (This is the same shock test to which the Microdetonator was subjected.) The shock was applied longitudinally to the detonator centerline and against the output end. Bridge resistances before and after the test were measured and recorded.

4.4 Header Assembly Function Time Test

The test setup is shown in Figure B-1, Appendix B. The two types of header assemblies (SOS 10362 and SOS 10507) were tested by capacitor discharge firing, and the function times were measured and recorded. The tests were performed with 1.0-, 4.7- and 22.0-microfarad capacitors at different voltage levels.

4.5 Header Assembly No-Fire Test

The test setup is shown in Figure B-1, Appendix B. A 30-shot constant current no-fire Bruceton test was performed on both types of header assemblies (SOS 10362 and SOS 10507). The test duration was 5 minutes. The test current was monitored and recorded. The "go" and "no-go" were recorded.

4.6 Detonator Dent Output Test

The test setup is shown in Figure B-2, Appendix B. The detonators were fired into witness plates at 0.250-inch test gap, and the function times were measured and recorded. The dent depths were measured and recorded.

4.7 Detonator Gap Test

The test setup is shown in Figure B-3, Appendix B. A 20-shot gap test was performed. This test showed the initiation of PBXN-5 boosters (with 0.005-inch-thick aluminum closure) by the detonators across variable air gap. Function times of the detonators were measured and recorded. The transfer and no-transfer were recorded.

4.8 Booster (Variable Closure) Initiation Test

The test setup is shown in Figure B-3, Appendix B. Test series were performed with both stainless steel and aluminum closure boosters. This test indicated the initiation of PBXN-5 boosters with either stainless steel closure (various thickness) or aluminum closure (various thickness) by the detonators across a constant air gap. Function times of the detonators were measured and recorded. The transfer and no-transfer were recorded.

4.9 Steel Barrier Test

The test setup is shown in Figure B-4, Appendix B. A 10-shot steel barrier test was performed. The effect on each steel barrier was observed and recorded. The detonator function times were measured and recorded.

SECTION V

TEST EQUIPMENT

5.1 Test Equipment

The MPD testing used the following major items of test equipment:

Firing Unit, SOS 54748 Capacitors (1.0, 4.7 and 22.0 microfarads) D.C. Power Supply (2 each) Oscilloscope, Tektronix, 555 Oscilloscope Camera, Polaroid Memoscope, Tektronix, 564B Velocity Test Box, SOS 06716 Current Probe Constant Current Source, SOS 06258 Digital Voltmeter, Hewlett Packard Detonator Firing Fixture Header Assembly Test Fixture Dial Indicator Feeler Gage Witness Plate, SOS 54134 Detonator Mounting Clips Leak Detector, Ion Equipment Corporation Temperature-Humidity Chamber, Conrad Air Gun (Launcher for Shock Test)

5.2 Special Test Fixtures

In addition to the standard items of test equipment, a number of special fixtures were made. These are shown in the figures of Appendix B.

SECTION VI

MEASUREMENT TECHNIQUES

The most difficult measurement to make reliably was the function time. Data obtained by several methods were found to be difficult to interpret and/or the response of the system too slow. The best method of measuring the function time was by monitoring the firing current and the Make-System.

When the primer charge initiates, ionization takes place and short-circuits the header leads. A sudden increase in firing current is noted at this time. The principle of ionization is also employed in the Make-System, as shown in Figure B-1, Appendix B. When the primer charge initiates, inization takes place and short-circuits the two Make-System contacts. This completes a circuit and discharges a charged capacitor which is monitored.

Figure B-10A, Appendix B, shows typical firing current traces through a deposited bridge (DB) -- top trace, and wire bridge (WB) -- bottom trace. The firing stimulus for these tests was the discharge of a 22-microfarad capacitor at 40 volts.

Figure B-10B shows typical header assembly firing current traces and Make-System output traces. Both Wire Bridge Header Assembly (WBHA) and Deposited Bridge Header Assembly (DBHA) were tested. The top trace and the one next-to-bottom are firing current and Make-System output of the same Deposited Bridge Header Assembly (SOS 10507) test, respectively. The second-to-top trace and the bottom trace are firing current and Make-System output of the same Wire Bridge Header Assembly test, respectively. Note that the time of the sudden current change nearly coincides with the Make-System output time.

Figure B-10C shows the firing current and Make-System output traces of Miniature Precision Detonator (MPD) tests. The MPD were tested as shown in Figure B-5A, Appendix B. The top and second-from-bottom traces of Figure B-10C are from a deposited bridge MPD (SOS 10314-103) test. The second-from-top and bottom traces are of a wire bridge MPD (SOS 10314-101 test. Note that there is about 0.8-microsecond difference between time of sudden firing current change and the Make-System output time of each MPD. This difference in time is the total time from the initiation of the transfer charge to the detonation of the output charge.

Figure B-5B shows the Make-System wiring for the development verification tests. This method is less repeatable but, if the wiring were done as shown in Figure B-5A, the output of the MPD would be distorted. In all tests, monitoring the firing current was the primary method of measuring the function time, and for the MPD tests, 0.8 ± 0.2 microsecond was added to the data to give the MPD function time. All traces were recorded by oscilloscope/camera. A memoscope was used as a redundant recording system.

SECTION VII

DATA ANALYSES AND CONCLUSIONS

7.0 General

The test data are given in Appendix C. A summary of the test data is given in Tables C-1 and C-2 of Appendix C.

7.1 Temperature-Humidity Test

After 17 days of the 28-day Temperature-Humidity (T&H) test, the MPD leads were noted to be rusting and some of the leads broken off. With the concurrence of AFATL by telephone, the T&H test was terminated after the 17-day exposure. One possible cause of rusting may have been due to some reaction caused by the residue Kester Paste Flux. The flux is activated and may not have been completely cleaned off with hot detergent water after the soldering operation.

A good quality nonporous gold plate is recommended as a possible method of minimizing this problem. Visual inspection showed that the other MPD parts were not affected mechanically by the T&H test.

For T&H test data see Appendix C, Table C-3, Data Sheets #1, #2 and #3 for the wire bridge and Sheets #19, #20 and #21 for the deposited bridge.

7.2 Shock Test

The shock test did not mechanically affect the MPD. The bridge resistance measured before and after the shock test revealed that all the resistances were about the same except for Specimen 338. The resistance increased by approximately 0.4 ohm.

For shock test data, see Appendix C, Table C-3, Data Sheets #4 for wire bridge and Sheet #22 for deposited bridge.

7.3 Header Assembly Function Time

The header assembly function time test data showed that the Wire Bridge Header Assembly (SOS 10362) will function in less than 10 microseconds with less than one microsecond jitter.

The minimum stimulus is the discharge of a 22-microfarad capacitor at 30 volts through the bridge. The minimum stimulus for the Deposited Bridge Header Assembly (SOS 10507) to meet the function time specification is the discharge of a 22-microfarad capacitor at 40 volts through the bridge. When the Deposited Bridge Header Assembly functions with any firing stimulus, the function time is always one microsecond or less.

For test data see Appendix C, Table C-3, as follows:

Wire Bridge Header Assembly:

Sheet 14 (Specimens 196-200) Sheet 15 (Specimens 201-205)

Deposited Bridge Header Assembly:

Sheet 37 (Specimens 571-575)

Sheet 38

Sheet 39 (Specimens 591-599)

7.4 Bruceton No-Fire Test

The no-fire test on the header assemblies showed that the \overline{X} no-fire level for the Wire Bridge Header Assembly and the Deposited Bridge Header Assembly is about 123 milliamperes with a standard deviation (S.D.) of 5.6 milliamperes for the Deposited Bridge and an S.D. of 3.9 for the Wire Bridge. The no-fire testing was conducted by the Bruceton method of Appendix A to NAVORD Report 2101. Calculations of the \overline{X} values are given below:

WIRE BRIDGE HEADER ASSEMBLY NO-FIRE

BRUCETON CALCULATION

				The state of the s
1	<u>X</u>	0	in _i	$\frac{1^2n_{\underline{1}}}{}$
0	0	2	G	0
1	2	7	7	7
2	7	5	10	20
3	3	_0_	0_	0
	n	= .14	A = 17	B = 27
	0 1 2 3	1 X 0 0 1 2 2 7 3 3	$ \begin{array}{cccccccccccccccccccccccccccccccccccc$	1 X 0 1 0 0 2 0 1 2 7 7 2 7 5 10 3 3 0 0

$$d = 5$$

$$A = 17$$

$$n = 14$$

$$\overline{X} = C + d \left(\frac{A}{n} \pm \frac{1}{2}\right) = 123.6 \text{ milliamperes}$$

$$M = \frac{nB - A^2}{n^2}$$

$$S = \frac{(M)}{0.623} + 0.056 = 0.785$$

$$S.D. = Sd = 3.924$$

DEPOSITED BRIDGE HEADER ASSEMBLY NO-FIRE BRUCETON CALCULATION

Current (milliampere)	<u>i</u>	X	0	in _i	i"n _i
115 120 125 130	0 1 2 3	1 3 3 3	2 2 2 0 n = 6	0 2 4 0 A = 6	$ \begin{array}{c} 0 \\ 2 \\ 8 \\ 0 \end{array} $ $ B = 10 $

$$C = 115$$

$$d = 5$$

$$\overline{X} = C + d \left(\frac{A}{n} \pm \frac{1}{2}\right) = 122.5 \text{ milliamperes}$$

$$M = \frac{nB - A^2}{n^2}$$

$$S = \frac{(M)}{0.623} + 0.056 = 1.126$$

$$S.D. = Sd = 5.630$$

For no-fire test data see Appendix C, Table C-3, Sheets #16 and #17.

7.5 Function Tests

All MPDs did not function. Recorded data indicated that the proper stimulus was applied to each unit. The firing stimulus for the Wire Bridge MPD (WBMPD) was the discharge of a 22-microfarad capacitor at 30 volts. For the Deposited Bridge MPD (DBMPD) the stimulus was the discharge of a 22-microfarad capacitor at 40 volts.

A smaller percentage functioned after being exposed to the shock test and T&H test. WBMPD Specimens 48 to 62 which were not exposed to any environmental test were functionally tested first. These all functioned with good function times. WBMPD Specimens 33 to 47 were shock-tested and functionally tested next. Two of the first 7 failed to function. The remaining 8 shocked WBMPD and the 15 shocked DBMPD were sent out for X-ray. The 2 failed units and 15 each of the two types of MPD which were not exposed to any environmental test were also sent out for X-ray as comparison units. The X-ray did not show any difference between the units.

Fifteen T&H WBMPD were functionally tested next, but several failed to function. These failed WBMPD, and the MPD which were X-rayed, were sent out to be N-rayed. The N-ray showed no difference between the units and showed that the sealed MPDs were not contaminated by flux. The 15 WBMPD N-rayed for comparison were not solder-sealed and, therefore, free of flux. Higher percentage of the DBMPD failed to function. All these MPD were solger-sealed.

Two failed-T&H MPD of each type were dissected on the output end, and the explosives were removed. A pressure of 45 psi was applied to the output end, and the header end was immersed in alcohol to check for possible leaks. There were no visible leaks. This indicates that the T&H failures were not due to moisture getting into the units.

Several of the failed units were dissected on the header end. These units showed blackening of the primer charge around the bridge area, due to the attempted functioning.

Unsoldered MPDs (Specimens 48 to 62, 72 to 100) all functioned. This indicated that another possible cause of failure may be due to overheating the parts during the soldering operation. An inert MPD with 0.00012-inch-diameter tungsten bridge was placed into the soldering fixture and heated with the RF-induction heater. The settings were the same as previously used. Tungsten bridge was used because of its high temperature coefficient of resistivity.

The resistance of the bridge was monitored during the heating cycle and the peak temperature calculated out to be approximately 550°F. It is known that lead azide will decompose at a higher temperature, and the effect of the temperature on the binder material (Viton "A") is unknown. The effects of overheating the primer charge are noted in the tests of Wire Bridge Header Assemblies that did not function during the no-fire test. Attempts were made to functionally test these units (Specimens 221, 222, 224, 226, etc.), but only one (Specimen 232) of 14 functioned.

It was noted the unsoldered MPDs (Specimens 48 to 62, 72 to 100) all functioned. All the header assemblies for the header assembly function tests and header assemblies built into MPDs were fabricated at the same time. An additional 30 deposited header assemblies were fabricated. Eight assemblies (Specimens 615 to 622) were tested for function time and all functioned properly. Twenty-two header assemblies were built into MPDs and tested without solder-sealing. These MPDs (Specimens 363 to 373, 378 to 388) all functioned properly.

For functional test data see Appendix C, Table C-3, as follows:

WBMPD: Data Sheets 1, 2, 3, 4, 5, 6, 7 and 8

DBMPD: Data Sheets 19, 20, 21, 22, 23, 24, 25 and 26

One can conclude from these tests that the major cause of the problem was due to the overheating of the MPDs during the soldering operation. The overheating probably decomposed part of the primer charge and may have weakened the adhesion strength of the binder so that the primer charge separated from the header during the shock test. This resulted in higher percentage of failures after the shock test.

The Microdetonator has the same primer charge configuration, and the detonator is not affected by the shock test. The primer charge is milled lead styphnate with 2% ethyl cellulose binder. The mechanical strength of the ethyl cellulose is stronger than Viton "A". This may be another possible reason why the Microdetonator will pass the test while the MPD does not.

The overheating problem can be resolved by using lower melting solder such as 50 Tin/50 Indium or using solder rings rather than solder sphere. Use of solder sphere requires longer heating time because the solder has to first melt and then flow around the header/case interface. A solder ring will require only enough heat to melt the solder since the solder is already located around the header/case interface.

Several WBMPDs (Specimens 74, 77, 86, and 100) had short function times of 3 microseconds or less. This was probably due to extreme deformation of the bridgewire at the weld joints or poor primer charge buttering which results in poor coupling between the wire and the primer charge. Both can cause hot spots on the wire. The cause of long function times of Specimens 65 and 82 can also be attributed to poor primer charge buttering. The primer charge buttering problem has been resolved as discussed in paragraph 3.2.3. Of the DBMPDs that functioned, all had function times between 1.1 to 1.6 microseconds.

Another fact noted was that no-function failure rate increased as the test progressed. See Appendix C, Table C-3, Sheet #23, where 3 of 15 units failed during dent output testing. compared to Sheet #26 which show 5 of 10 failures. The data suggest there may be a long-term storage problem using lead azide as the primer charge or, as in this case, the lead azide (primer charge) continued to decompose after the lead azide was partially decomposed during the soldering operation by overheating. This can be verified by storing some parts and periodically testing a few units. All the test hardware, with a few exceptions, were fabricated approximately one month before the first test specimen was functionally tested.

7.6 Effect of Environment Exposures

The dent output test data show that the environmental tests did not affect the MPD output, and the dent output ranged between 0.028 to 0.046 inch.

Refer to Appendix C, Table C-3, data sheets for environmental test data as follows:

	DATA SHEET	NUMBERS
ENVIRONMENT	WBMPD	DBMPD
Т&Н	1, 2, 3	19, 20
Shock	4,5	22
No environments	б	23

7.7 Gap Transfer Capability

The gap test data show that the MPD with dimpled can will initiate a PBXN-5 booster with 0,005-inch-thick aluminum closure reliably across a 0.075-inch air gap or less. In later tests with the flat-bottomed can, 5 out of 5 transfers occurred at 0.250-inch gap into a PBXN-5 acceptor with a 5-mil aluminum closure. These data are not included in the following analysis.

See Appendix C, Table C-3, Sheet #7 and Sheet #8 (Specimens 87-91) for test records relating to gap transfer.

Using the test data in a Bruceton calculation provides:

GAP TRANSFER
BRUCETON CALCULATION

Gap (inch)	_1_	_X_	0	ini	i ² n _i
0.075 0.100 0.125 0.150	0 1 2 3	1 6 2 0 n = 9	O 1 4 4	A = 10	B = 14

$$C = 0.075$$

 $d = 0.025$
 $A = 10$
 $n = 9$

$$\overline{X}$$
 = C + d $(\frac{A}{n} \pm \frac{1}{2})$ = 0.115 inch

$$M = \frac{nB - A^2}{n^2} = 0.321$$

$$S = \frac{(M)}{0.623} + 0.056 = 0.571$$
S.D. = Sd = 0.014

7.8 MPD Closure

The booster initiation test data show that the maximum closure thickness through which the MPD will reliably initiate PBXN-5 at 30 Kpsi is estimated as 0.005 inch. This is for both aluminum and stainless steel closure. The air gap was 0.075 inch.

For test data see Appendix C, Table C-3, as follows:

Aluminum closure:

Sheet 8 (Specimens 92 to 96) Sheet 24

Stainles steel:

Sheet 8 (Specimens 97 to 100) Sheet 25

7.9 Barrier Tests

The barrier test data show that it requires three 0.022-inch-thick stainless steel barriers to confine the MPD output. Stainless steel, dimpled cases were used in all these tests.

See Appendix B, Figure B-4, for test setup.

Test data are recorded in Appendix C, Table C-3, as follows:

T&H shots:

Sheet 20 (Specimens 321, 322, 323, and 328) Sheet 21 (Specimen 332)

Nonenvironmental shots:

Sheet 26

7.10 Flat Bottom Can Tests

Tests were conducted initially with stainless steel cases, dimpled in the same configuration as the standard Microdetonator. Past experience with the aluminum cases of the Microdetonator showed better performance in gap transfer if the aluminum cases were shaped in a concave manner, similar to a conical-shaped charge.

The stainless steel, dimpled cases were noted to be inferior to aluminum in transfer capability. Stainless steel cases transferred reliably at 0.075 inch compared to as much as 1.0 inch for aluminum. The stainless steel case walls were reduced to about 0.002 inch to bring the mass equivalency closer to the aluminum cases.

Gap firings with the 0.002 inch dimpled, stainless steel cases showed reliable transfer at approximately 0.100 inch, still much less than the equivalent aluminum cases.

The poor results with the "flying plate" approach with stainless steel cases suggested trial of normal fragmentation as obtained from flat-bottomed cases.

Accordingly, 14 flat-bottomed units were assembled. Three were fired for dent output with results as follows:

Gap (inch)	Dent Output (inch)
0.500	0.020 0.020
0.250 0.150	0.020

Dent tests at 0.250-inch gap with stainless steel, dimpled cases averaged approximately 0.035-inch dent output.

The dent depth firings were made for a gross evaluation of the fragmentation coverage and depth relative to the several selected gap distances. Dent depth is not a good criterion in evaluating the effectiveness of transfer but is valid only as an indicator of relative consistency of output between similar units. To draw conclusion about the gap transfer effectiveness, the remaining ll units were fired into PBXN-5 boosters having 0.005-inch aluminum closures. Results were:

Gap Distance (inch)	Transfers/Tests
0.250	5/5
0.500	4/6

This showed that flat-bottomed, stainless steel cases were superior to dimpled ones. It is, therefore, recommended that the stainless steel test configuration be standardized on flat-bottomed cases in all future tests.

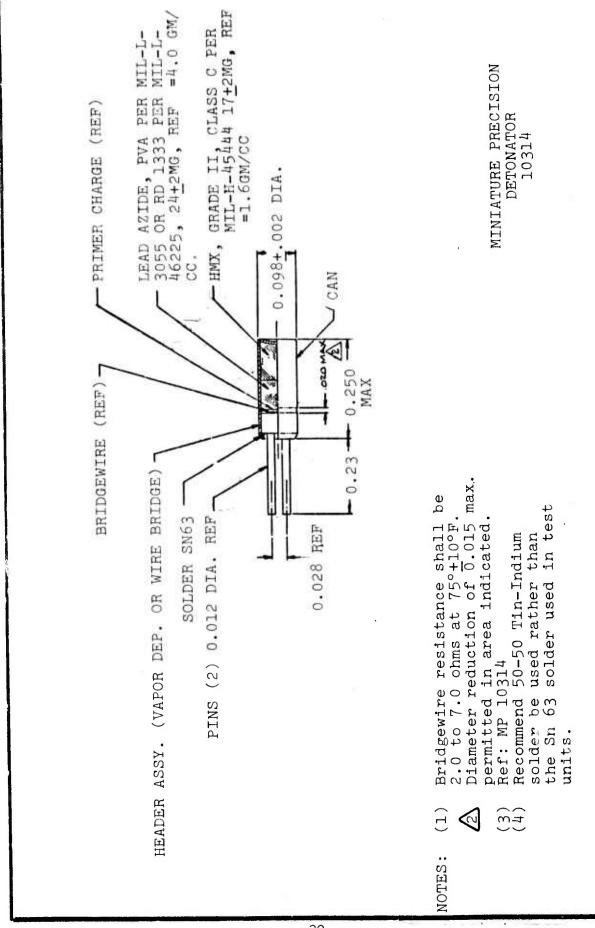
For test records see Appendix C, Table C-3, Sheets #44 and #45.

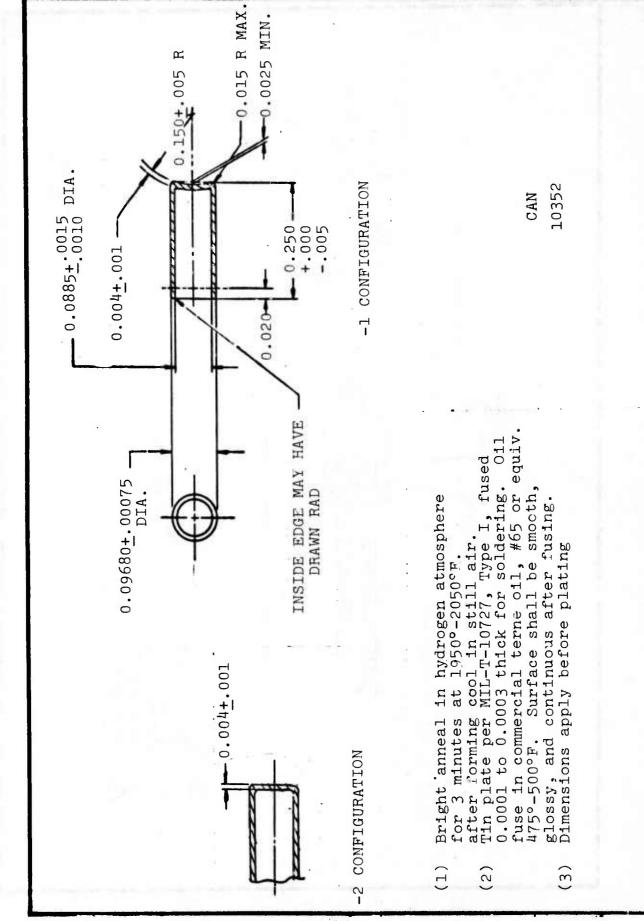
7.11 RADC Reliability Evaluation of Deposited Bridge Headers

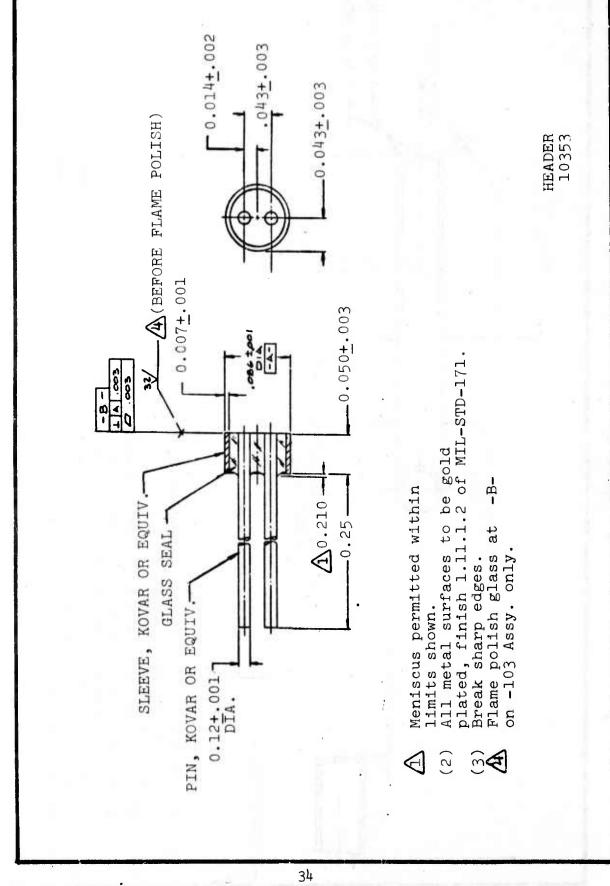
Appendices D and E contain an evaluation of deposited headers of both a single pin configuration (PN 08892) and the two pin DBMPD (PN 10506). These evaluations clearly indicate deficiencies in the manufacturing techniques. Additional work is requried in this area to insure adequate shelf life and reliability necessary for field use.

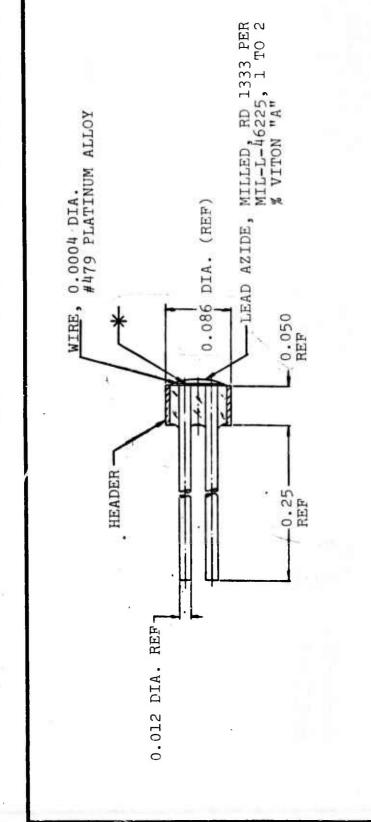
APPENDIX A

DRAWINGS



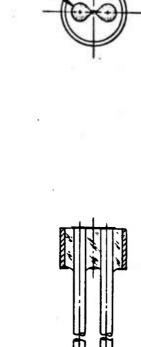






header surface between the two pins. Headers will be inspected visually and sorted to eliminate recession. No recession is allowed in the NOTE:

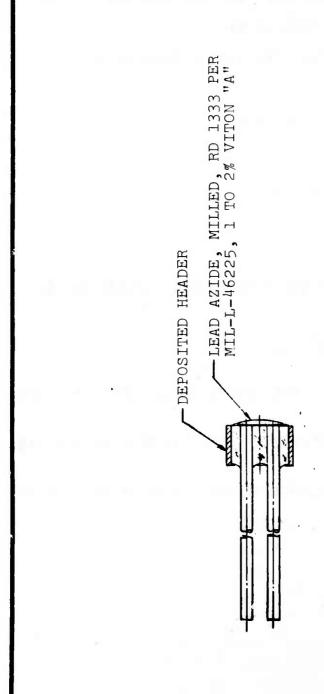
HEADER ASSEMBLY



CHROMIUM BASE PLUS
40008 PALLADIUM (USE
MASK AND FIXTURE 54799.)
RESISTANCE - 2.0 TO 5.0
OHMS AT 75°+ 10°F.

-HEADER

DEPOSITED HEADER

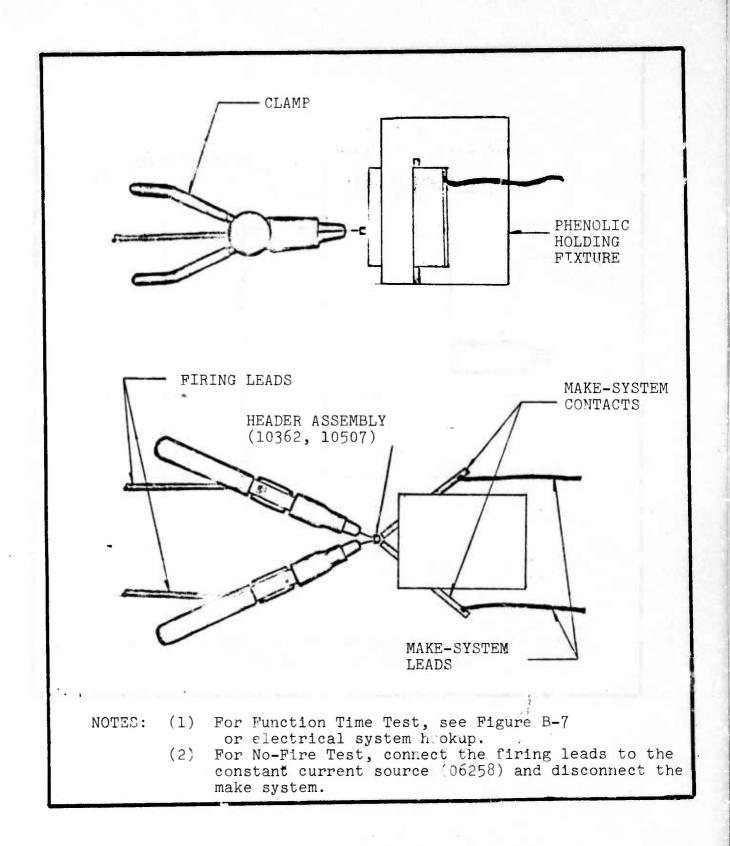


HEADER ASSEMBLY

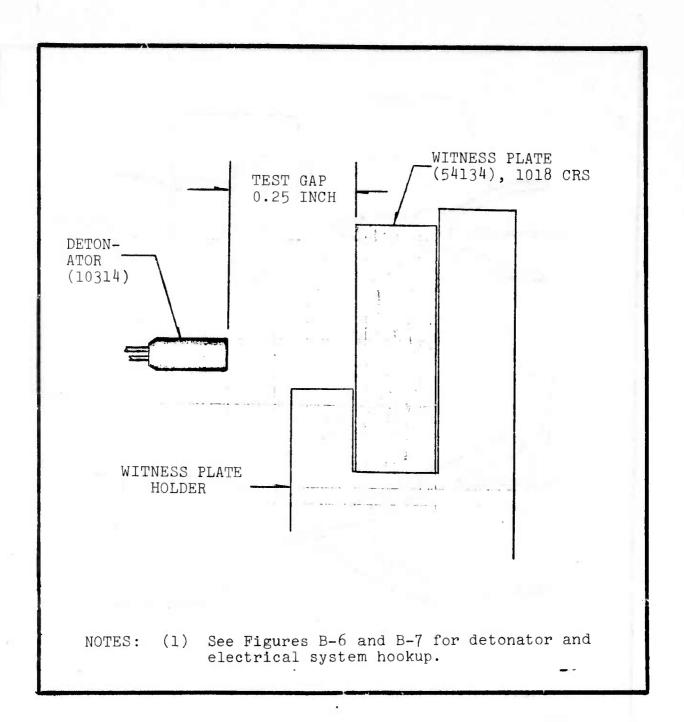
APPENDIX B

Figures

B-1	HEADER ASSEMBLY FUNCTION TIME AND NO-FIRE TEST SETUP
B-2	DETONATOR DENT OUTPUT TEST SETUP
B - 3	DETONATOR GAP AND BOOSTER INITIATION TEST SETUP
B-4	STEEL BARRIER TEST SETUP
B-5	DETONATOR MAKE SYSTEM TEST SETUP
B - 6	DETONATOR TEST SETUP
B-7	ELECTRICAL SYSTEM SCHEMATIC
B-8	VAPOR DEPOSITION SETUP
B - 9	HEADER ASSEMBLY
B-10	TYPICAL FIRING CURRENT AND MAKE SYSTEM OUTPUT TRACES
	Tables
B-1	DEPOSITED BRIDGE RESISTANCE VERSUS LOCATION ON FIXTURE RUN #1
B-2	DEPOSITED BRIDGE RESISTANCE VERSUS LOCATION ON FIXTURE RUN #2
B-3	DEPOSITED BRIDGE RESISTANCE VERSUS LOCATION ON FIXTURE

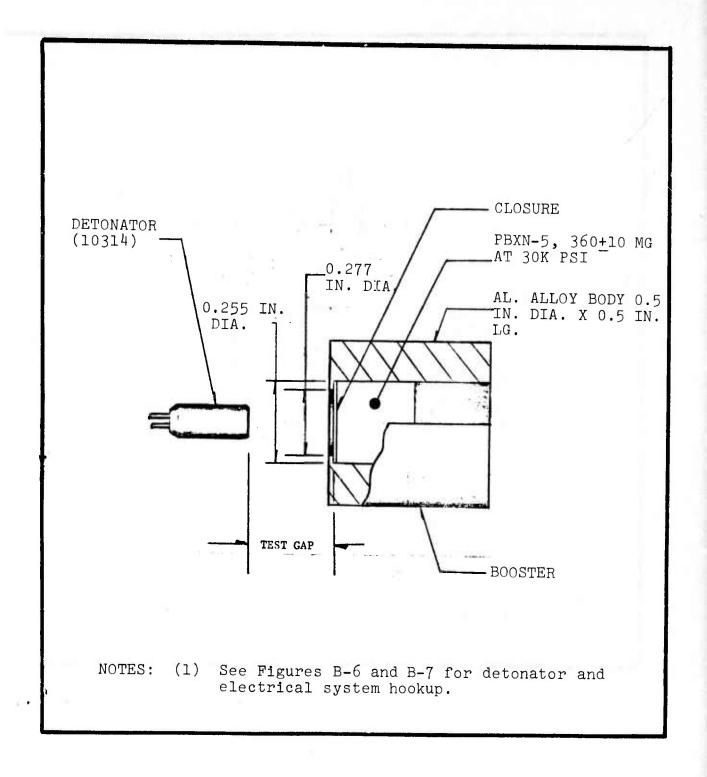


Header Assembly Function Time and No-Fire Test Setup



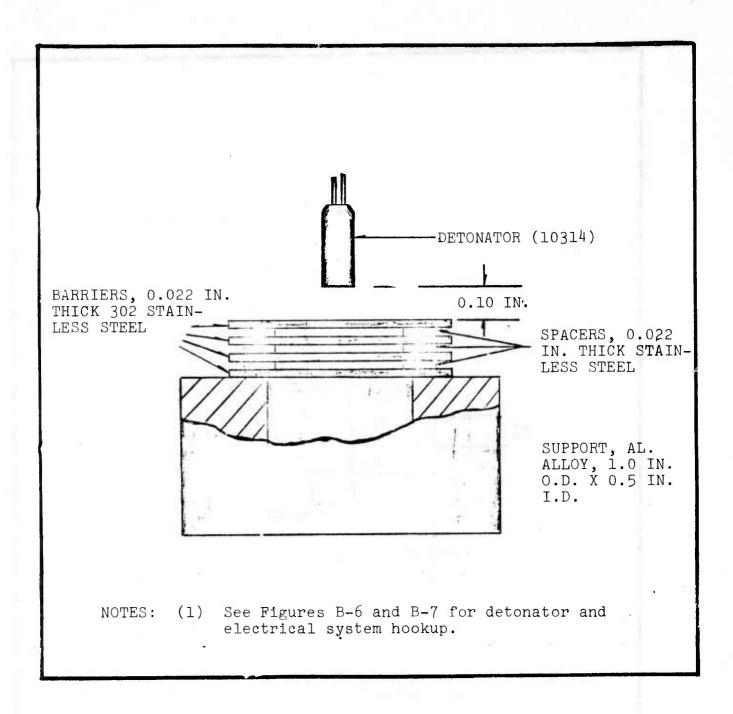
Detonator Dent Output Test Setup

Figure B-2

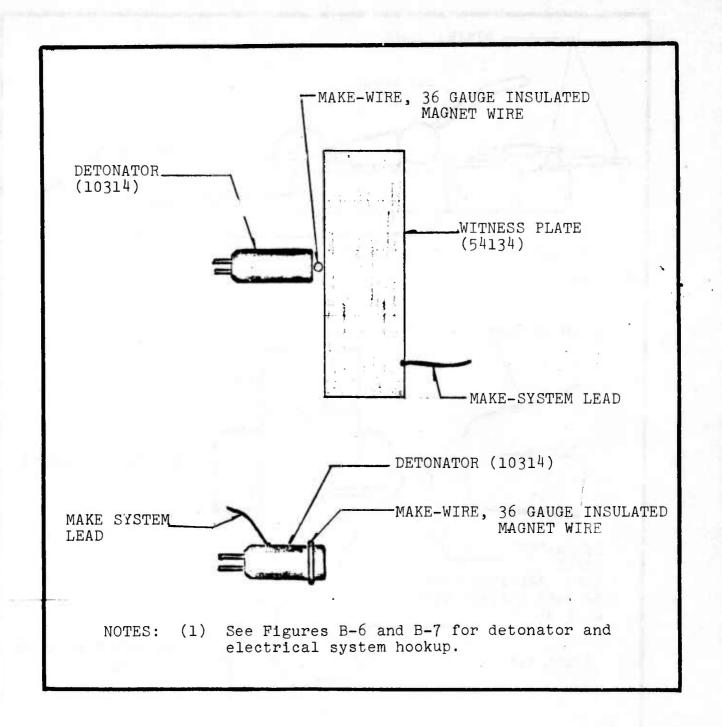


Detonator "Gap" and Booster Initiation Test Setup

Figure B-3

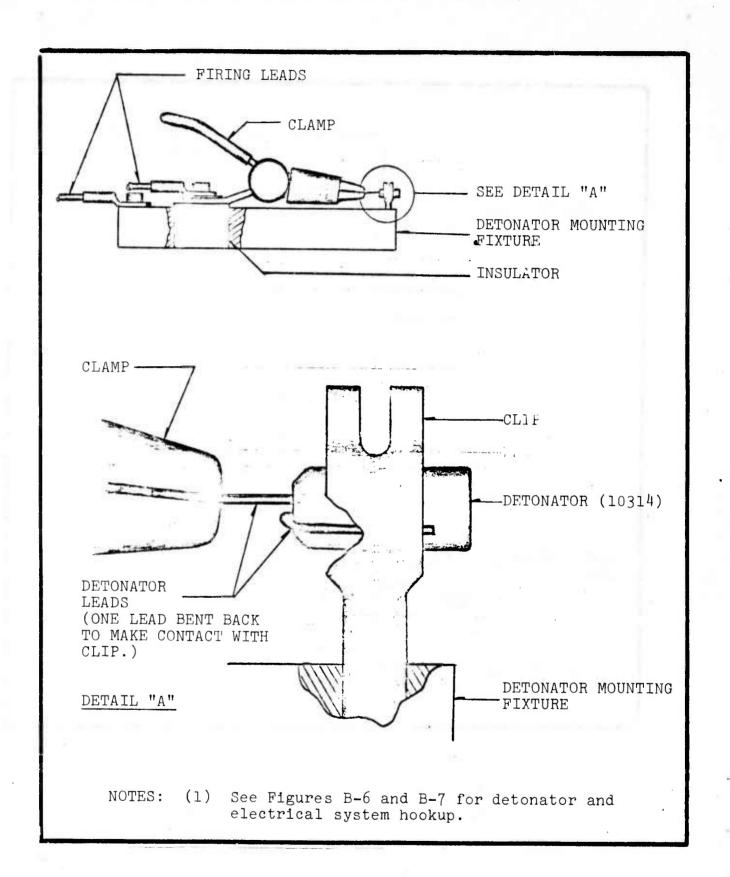


Steel Barrier Test Setup
Figure B-4



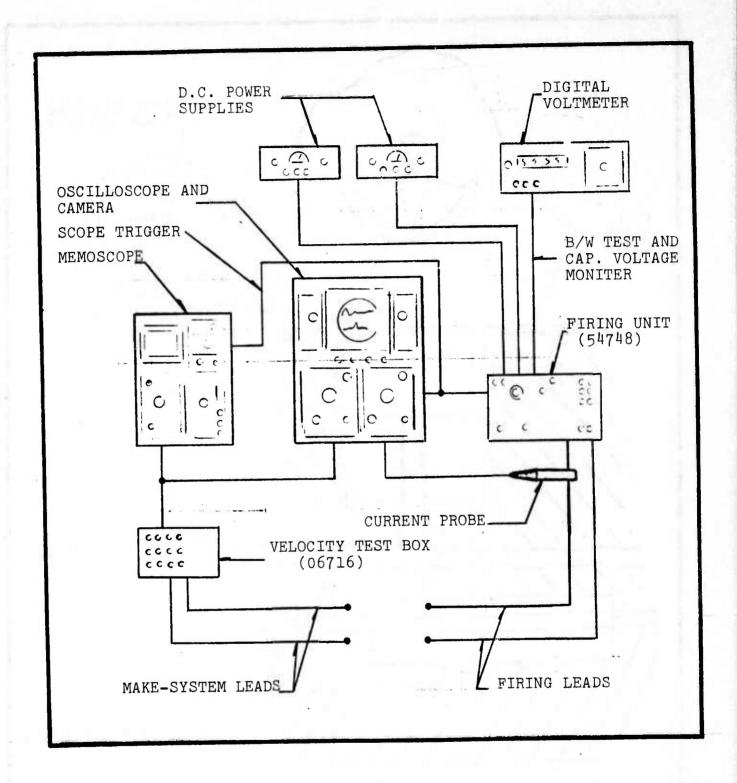
Detonator Make System Test Setup

Figure B-5

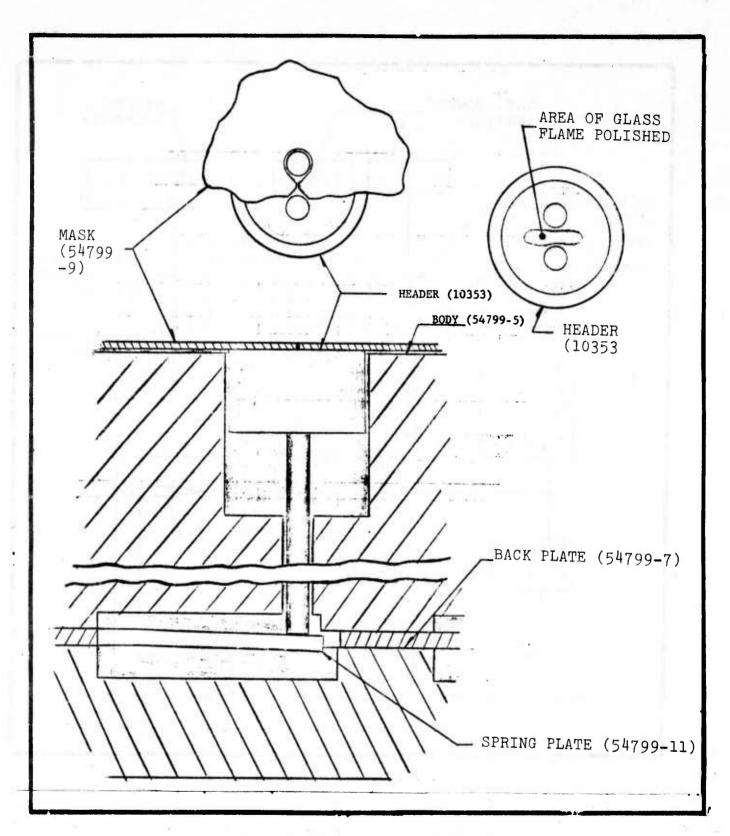


Detonator Make System Test Setup

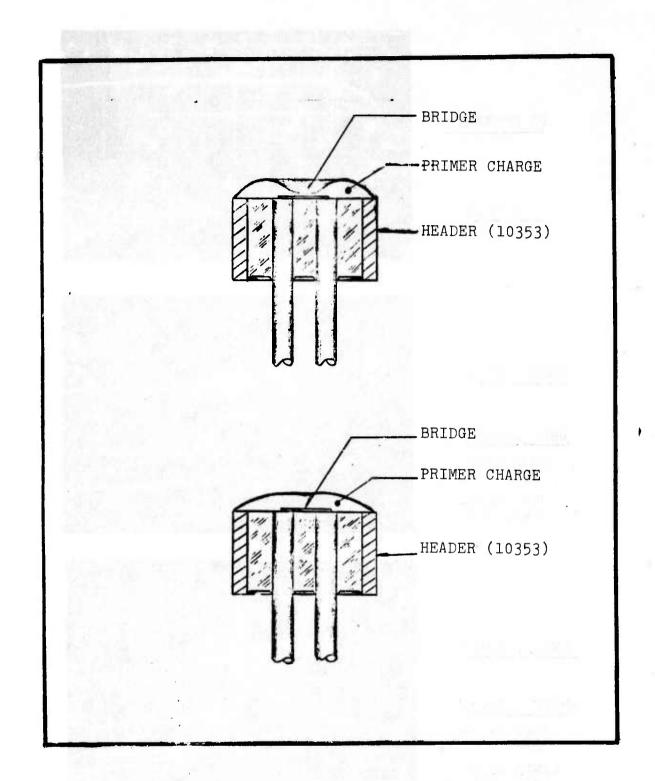
Figure B-6



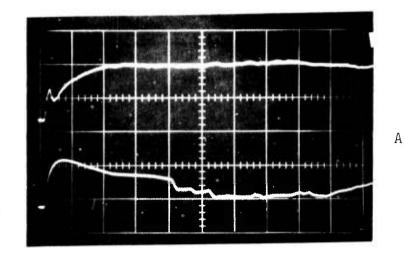
Electrical System Schematic
Figure B-7



Vapor Deposition Setup
Figure B-8



Header Assembly
Figure B-9



DB CURRENT

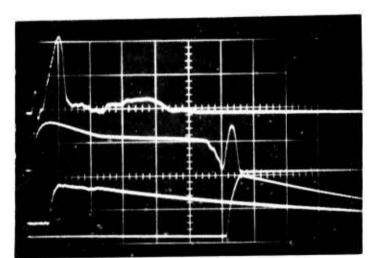
WB CURRENT

DBHA CURRENT

WBHA CURRENT

DBHA MAKE-SYS. OUT.

WBH MAKE-SYS. OUT.



В

C

DBMPD CURRENT

WBMPD CURRENT

DBMPD MAKE-SYS. OUT.

WBMPD MAKE-SYS. OUT.

For all traces Sweep rate: 1 Usec/cm

Oscillograph Records
Figure B-10
48

	TABLE B-2 DEPOSITED BRIDGE RESISTANCE VERSUS LOCATION ON FIXTURE - RUN NO. 2
RUM N	0. 2 Cr THICK DAM/SQUARE CRN P/N DATE 200 A 4300 A .72 4264 10506 4-11-74
	1 2 3 4 5 6 7 8
П	5.246.795.035.144.036.225.104.855.215.915.746.556.099.007.246.215.565.647.09PEN
2	3.435.534.425.104.324.435.344.845.334.265.055.356.685.815.465.045.565.144.845.42
m	5.284.530PEN5.554.524.305.435.184.809.005.625.575.996.963.944.714.336.288.459.06
7	3.174.413.823.884.224.314.004.354.124.786.004.724.585.155.743.9715224.364.845.11
ī	3.863.304.324.434.303.754.433.793.693.984.004.853.804.034.833.604.563.884.104.53
9	3.934.103.284.143.453.873.844.227.993.924.434.904.734.563.493.304.639.513.634.50
7	3.9014849.454.203.543.743.573.774.083.684.674.274.274.004.025.174.734.254.236.16
ω	3.463.820PEN3.704.803.243.573.723.654.203.584.164.254.214.073.574.153.843.873.69
9	3.213.443.862.864.473.993.333.463.173.683.473.393.563.753.573.293.453.323.633.86
10	3.753.093.683.603.303.532.993.303.50 3.833.763.533.173.593.403.594.203.38
11	3.143.533.953.673.463.273.653.033.38 3.813.703.613.273.143.453.553.473.44
12	3.256.203.363.253.383.003.453.033.442.923.072.952.773.522.923.053.183.203.36
13	3.403.272.902.903.436.572.892.974.605.713.002.833.543.172.723.093.003.692.793.17
14	6.16 3.41 3.11 6.12 3.16 3.35 3.06 3.34 3.89 3.05 3.05 2.92 2.90 2.78 2.72 3.70 2.99 2.86 3.09 3.08
15	3.566.473.153.102.952.603.255.973.332.743.033.222.873.152.903.042.762.903.133.26
16	3.723.273.133.283.283.083.043.512.782.892.702.842.773.103.282.882.763.573.252.98
17	3.143.602.983.063.132.943.212.972.782.762.862.832.723.102.772.882.692.913.053.30
18	3.444.072.763.333.213.233.783.453.102.722.723.092.802.953.012.902.662.832.983.36
19	4.783.373.133.173.064.653.403.339.603.053.062.633.442.874.233.153.602.882.902.86
20	5.584.473.923.293.563.0921604.022.913.443.003.193.253.913.523.233.713.663.102.90

TABLE B-3 DEPOSITED BRIDGE RESISTANCE VERSUS LOCATION ON FIXTURE - RUN NO.

18 2.102.172.342.232.792.153.1011.8411.922.0711.9811.9011.841.902.0241.301.972.031.972.072.652.26 19 2.822.992.242.452.302.182.102.372.201.902.022.522.182.422.112.301.912.072.652.26 20 3.602.782.973.672.182.012.183.022.661.642.162.352.232.442.472.520PENZ.392.102.32
3.602.782.973.572.182.012.183.022.661.642.162.352.232.442.472.520PEN2.392.102.3

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APPENDIX C

TEST DATA TABLES

MPD	OUTPUT	D DA	ATA SU	JMMARY	ľ	C-1
MPD	FUNCTI	ON	TEST	DATA	SUMMARY	C-2
TEST	r DATA	SHE	EETS			C-3

		RESULTS APPEAR ON DATA SHEETS	1,2,3,19,20	& 22	5, 6, & 23	~					8 & 24				8 & 25							
	ATION	NO. OF TRANSFER				0	0	2	9	Ţ	0	77	3	7	0	7	0	Ľ				
IARY	FER INITIATION	CLOSURE THICK (IN)				0.005	0.005	0.005	0.005	0.005	0.025	0.020	0.016	0.010		0.015	0.010	0.005				
TABLE C-1 OUTPUT DATA SUMMARY MPD, P/N 10314	BOOSTER	CLOSURE TYPE				AL	AL	AL	AL	AL	AL	AL	AL	AL	ς δ	S.S.	S.S.	s.s.				
	DENT	MAX. (IN)	0.046	0.042	0.046																	
Q g M	OUTPUT	MIN. (IN)	0.023	0.030	0.028																Closure	
	MPD	AVE. (IN)	0.037	0	0.035															ure	Steel	
		NO. OF TEST	23	14	36	2	7	9	7	1	2	7	9	5	~	ဘ	2	٦		Aluminum	Stainless	
		TEST GAP (IN)	0.250	•	0.250	0.250	0.150	0.125	0.100	0.075	0.075	0.075		0.075		0.075	0.075	0.075		= Alu	. = Sta	
		ENVIRON-	T&H	SHOCK	N	0		ш		> 5l4	н	oc; o); 	2, 5	Ξ Ш	Z	E	Ø	NOTE:	AL	 	

		RESULTS APPEAR ON DATA SHEETS	6	01	10		11, 11	11, 12		12	13	13	
IRY	FUNCTION TIMES	TIMES OUT OF SPEC.								9.1	6.3		
SUMMA		NO. IN SPEC								6	6		
TABLE C-2 MPD FUNCTION TEST DATA SUMMARY		TIME RANGE WITHIN + 1 uSEC TOLER.			5.1, 6.8, 9.6, 220, 240, 290, 315, 390, 440	10.5,11.1, 12.2,12.5, 13.8,13.9, 14.1,14.4,	• 1	0,17.0	21.0,22.5, 23.5,24.0,	7.0-8.8	-5.1	35.5,37.5, 40.5,40.5,	
T	FUNCTION	NO. FUNC	0	7	o ·	10	c	10		10	10	r)	sealed
PU GS	FUNC	NO. OF TEST	ľ	101	10	CT CT	L	100		10	10	5	er sea
H		CAP VOLT (VOLT)	ır	20	30	0 17	l.	20		30	07	Z.	solde
		CAP CAP VOLT (µFD)(VOLT)	1.0) 	<u> </u>		-	<u>,</u>		1		22	e not
		ENV.					L.					4	MPD are
-		P/N	10362	1000									3
		PART	 - 	ASSV	1000								NOTE:

Continued	IMES	RESULTS APPEAR ON DATA SHEETS	14		14, 15	15	27		28, 29	١.		-	•	32, 33		25 25			37, 38, 39, 40,		2	
X	FUNCTION TIM	TIMES OUT OF SPEC.																				
SULMARY		NO. IN SPEC			10	10			C		07		3	14	19			77-	37	-	14	
ABLE C-2 TEST DATA		TIME RANGE WITHIN + 1 µSEC TOLER.	10.6	12.2,13.6,	1				L	•	0.4-0.9		0.8-1.0	.5-0	0.45-0.7		7	110	0.3-0.6		0.4-0.6	
T	FUNCTION		6		10	10	0	0	0	10	7	0	3	14	19	С	0-	+	37	,	7.4	sealed
	FUNC	I [10		10	10	77	Υ.	07	20	02	710	10	20	20	5	10	070	37)	15	solder s
MPD		CAP VOLT (VOLT)	20		30	07	15	10	20	30	0 1	10	20	30	10	5	10	20	200	2	30	not sol
		CAP (µFD)	22		I	-	0 - [<u> </u>		4	7 11	r				22					147	are no
		ENV.																				MPD
		P/N	10362				10507														. 4. 41.41.	S: (1)
		PART	HDR	ASSY			ــــــــــــــــــــــــــــــــــــــ	YSSA 26	1													NOTES:

						TA	TABLE C-2			
				MPD		FUNCTION	TEST DATA SI	SUMMARY	7	Concluded
					FUNC	FUNCTION			FUNCTION TIMES	S
PART	P/N	ENV.	CAP (µFD)	CAP CAP VOLT (µFD)(VOLT)	NO. OF TEST	NO. FUNC	TIME RANGE WITHIN + 1 µSEC TOLER.	NO.' IN SPEC	TIMES OUT OF SPEC.	RESULTS APPEAR ON DATA SHEETS
WBMPD	10314-	Т&Н	22	30	18	15	5.4-7.1	10	7.5, 7.9, 9.4	1, 2, 3
	+ > +	SHOCK	22	30	15	10	5 9-7.6	5	8.8, 9.0, 16.	7. 8
			22	30	6	6	6.6-8.5	9		9 0
WBMPD	10314- 101 (1)		22	30	ከ ከ	ħħ	6.0-8.0	32	8.7. 8.0. 8.0. 8.0. 8.0. 8.3. 8.3. 8.3. 8.3	7, 3, .0 5, 7, 8
рамер	10314-	Т&Н ЅНОСК	22 22 22	017	23 1 5 33	13	1.3-1.6 1.3-1.6 1.1-1.5	13 4		19, 20, 21 22 23, 24(374-377), 25(389-392), 26
DBMPD	10314-		22	40	25	22	1.1-1.3	22		(363-373)
NOTES:	: (1)	MPD a	are not	sol	der se	sealed				

	LOPMENT				NCTION T			,	10314-			
PREC	ISION DE	TONATOR		(15)	NO.	7 - 5- 4	42	264		MENT -	T &H	
4 -	22-74		28-7		70°F		52	%		ا ۱۱۰ سا		D F 10
SPE	CLEN	(1)	I	CAP.	TEST (2)	TEST	BOOS	TER	DE	TOLATOR	SULTS	
NO.	B/W (OHM)	TEST CONFIG.	CAP. (UFD)	VOLT.	B/W (OHM)	GAP (IN)	CLOS TYPE		FUNC.	FUIC.	DENT	BOOST. FUNC. (YTS/N
	4.46				4.92				SEE Note 3			
ż	4.17	c	22	30.0	4.15	0.25			YES	6.3	0.040	
3	4.24				4.14				NOTE 3			
4	4.49				3.08				SEB Note 3			
5	4.21								SEE NOTE 3			
G	4.31								SATE S			
7	4.21	c	22	30.0	4.19	0.25			No.			
8	4.20	c	22	30.0	4.17	0.25			YES	7.9	0.034	
9	4.33	c	22	30,0	4.32	0.25			YES	6.2	0.046	
10	4.28								SEE Note 3			
1)	4.61				4.37				SEE NOTE 3			
12	4.28	c	22	30.0	4.28	0.25			YES	9.6	0.034	
13	4.46								SEE NOTE 3			
14	4.25	c	22	30.0	4.24	0.25			YES	10.6	0.035	
15	4.46	c	22	30.0	4.43	0,25			YES	6.1	0.036	

- (1) Test Configurations --
 - A Header Assembly Function Time Test (Figure B-1)
 - B Header Assembly "No-fire" Test (Figure B-1)
 - C Detonator Dent Output Test (Figure B-2)
 - D Detonator Gap Test (Figure B-3)
 - E Booster (Variable Closure) Initiation Test (Figure B-3)
 - F "Steel Barrier" Test (Figure B-4)
- (2) Bridgewire Resistance After T&H Test
- (3) Broken Lead

DEVE	LOPEINT				UNCTION				103	14-101		. ,
PREC	ISION DE	TONATOR			1 to 1,			4264	ENVIRON			ALA,
4-	22-74		28-7		70°F	4		2 %	1151	FG IPT	1 -2 7 -2, 1	
SPE	CEIEN	/ / / /	ı		TEST		1 110	OSTER		TOST P	ESULTS	
NO.	B/W (OHM)	TEST CONFIG.	CAP.	CAP. VOLT. (VOLT)	B/≒/ (OHM)	GAP (IN)	CL	OSURE THIC	FUNC.	FUNC.	DENT	BOOST. FUNC. (YUS/N
16	4.13	e	22	30.0	4.11	0.250			Yes			(11.5/1.
17	4.44				4.23				SER Note 3			
18	4.29	c	22	30.0	4.14	0.25	9		YES	6.8	0.037	
19	4.31	c	22	30.0	4.16	0.25	<u> </u>		No			
20	4.07	c	22	30.0	3.92	0.250	,		YES	9.4	0.040	
21	4.44	c	22	30,0	4.28	0.250	,		YES	5.7	0.032	
22	4.35								SEE Abte 3			
23	4.49	e	22	30.0	4.33	0.250	,		YES	7./	0 933	
24	4.40				4.25				SEE NOTE 3			
Z <i>5</i>	4.55				4.38				SEE NOTE 3			
26	4.29	c.	22	30.0	4.16	0.250			YE5	7.5	0.040	
27	4.14	c	22	30.0	3.99	0250			YES	5.4	0.035	
28	4.50	c	22	30.0	4.33	0.250			No			
29	4.30	С	22	30.0	4.17	0.250			YES	4.5	0 036	
30	4.19								Note 3			

- (1) Test Configurations --
 - A Header Assembly Function Time Test (Figure B-1)
 - B Header Assembly "No-fire" Test (Figure B-1)
 - C Detonator Dent Output Test (Figure B-2)
 - D Detonator Gap Test (Figure B-3)
 - E Booster (Variable Closure) Initiation Test (Figure B-3)
 - F "Steel Barrier" Test (Figure B-4)
- (2) Bridgewire Resistance After T&H Test
- (3) Broken Lead

	LOPMENT			FU	NCTION	SENSIT	IVITY/		10314-			
PREC:	NAMI MI	TONATOR		1.0	E NID.	1-11-11	42	64	ENVIRON	MENT -	TCH	
4-	22-74	5-	2 <i>8</i> -7		70°		52		1 3 mg 1	FULLEP 11	VF ~ 10	nr as
SPE	<u>DÆN</u>				TEST					7771	S'JLTS	
NO.	B/W (OHM)	TEST CONFIC.	CAP.	CAP. VOLT. (VOLT)	(2) B/W (OHM)	TEST GAP (IN)	BOOS CLOS TYPE	THICK.	FINC	FUIC.		BOOST. FUNC. (YES/NO
31	4.28	c	22	30.0	4.16	0.250			YES	6.8		
32	4.43				4.28				SEE NOTE 3			
-												
	N											
				-	8							
	·											

- (1) Test Configurations --
 - A Header Assembly Function Time Test (Figure B-1)
 - B Header Assembly "No-fire" Test (Figure B-1)
 - C Detonator Dent Output Test (Figure B-2)
 - D Detonator Gap Test (Figure B-3)
 - E Booster (Variable Closure) Initiation Test
 - (Figure B-3, F "Steel Barrier" 'lest (Figure B-4)
- (2) Bridgewire Resistance After T&H Test
- (3) Broken Lead

	OPENT		-		4 11 E 7 a se				10314-			
PA 1/ 1	ISION DE			FU	NCTION I	ME/OU	1 to 5	64	14 (2 + 1) =	MENT -		A / A
	STANT		CUNIFIC	T F A	4 FE T 1	P. B1		11011		- 12 41		11 ~
	2-74	5-2	28-74		70°F		52°	/0			,	
SPE	CIMEN				TEST		BOOS	ጥማን	17.75	TEST RE	SULTS	
NO.	B/W (OHM)	TEST CONFIG.	CAP. (UFD)	CAP. VOLT. (VOLT)	(2) B/W (OHM)	TEST GAP (IN)	CLOS		FUNC.	FUNC.	DENT (IN)	BOOST. FUNC. (YES/NO
33	4.62	c	22	30.0	4.57	0.250			YES	9.0	0.037	
34	4.20	c	22	30.0	4.18	0.250		ļ 	YES	16.8	0.034	
35	4.11	C	22	30.0	4.10	0.250			No			
36	4.51	C	22	30.0	4.48	0.250			465	8.8	0.032	
37	4.55	c	22	30.0	4.53	0.250			YES	7.3	0.031	
38	4.47	c	22	30.0	4.42	0.250			No			
39	4.38	e	22	30.0	4.34	0.250			YES	7.6	0.030	
40	4.47	c	22	30,0	4.43	0.250			YES	5.9	0.05	
41	4.39	С	22	30.0	4.37	0.250			YES	>20.0	0 038	
42	4.50	c	22	30.0	4.47	0:250			YES	6.5	0.030	
43	4.46	c	22	30.0	4.42	0:250			No			
44	4:19	c	22	30.0	4.15	0.250			YES	>20.0	0.035	
45	4.30	c	22	30.0	4.26	0.250			No			
46	4.46	c	22	30.0	4.45	0.250			No			
47	4.29	C	22	30.0	4.27	0.250			YES	7.0	0.031	

- (1) Test Configurations --
 - A Header Assembly Function Time Test (Figure B-1)
 - B Header Assembly "No-fire" Test (Figure B-1)
 - C Detonator Dent Output Test (Figure B-2)
 - D Detonator Gap Test (Figure B-3)
 - E Booster (Variable Closure) Initiation Test (Figure B-3)
 - F "Steel Barrier" Test (Figure B-4)
- (2) Bridgewire Resistance After T&H Test
- (3) Broken Lead
- 6.

DEVEL	OPMENT					SENSIT			10314-1	.01		
	SION DET				fair i	1 1			r is to t D			NA N
1 4	14-74	11 51	28-7	1	70 ° F	131	50	2/0	* ** ! ·	a 111 e	71 345	14
SPEC	IMEN				TEST	BOOSTER			D.:	TEST KE TOUVEN	SULTS	
NO.	B/W (OID1)	TEST CONFIC.		CAP. VOLT. (VOLT)		TEST GAP (IN)	CLOS TYPE		FUNC. (YES/No	FUIC.	DENT (IN)	BOOST. FUNC. (YES/N
48	4.08	c	22	30.0		0.250			YES	6.5	0.031	
49	4.02	و	22	30.0		0.250			YES	7.2	0.032	
50	4.39	c	22	30.0		0.250			YES	6.4	0.039	
51	3.90	c	22	30.0		0.250			YES	6.0	0.036	
5z	4.26	c	22	30.0		0.250			YES	8.0	0.035	
53	4.29	c	22	30.0		0.250			YES	6.1	0.034	
54	4.03	c	22	30.0		0.250			YES	6.3	0.044	
55	4.29	c	22	30.0		0.250			YES	7.6	0.040	
54	4.19	c	22	30.0		0.250			YES	7.2	0.029	
51	4.29	c	22	30.0		0.250			YES	6.0	0.032	
58	4.12	c	72	30.0		0.250	_		YES	6.8	0.038	
59	4.04	c	22	30.0		0.250			YES	6.2	0.034	
60	4.13	c	22	30.0		0.250		ļ	YES	7.6	0.042	ļ
61	4.06	c	22	30.0		0.250			YES	7.1	0.035	1
62	4.03	C	22	30.0		0.250			Y65	6.6	0.036	

- (1) Test Configurations --A - Header Assembly Function Time Test (Figure B-1)
 B - Header Assembly "No-fire" Test (Figure B-1)

 - C Detonator Dent Output Test (Figure B-2)
 - D Detonator Gap Test (Figure B-3)
 - E Booster (Variable Closure) Initiation Test
 - (Figure B-3) F - "Steel Barrier" Test (Figure B-4)
- (2) Bridgewire Resistance After T&H Test
- (3) Broken Lead

DEVE	OPMENT					" SENSIT		'	10314			
PRECI	SION DE	TONATOR				1 1 1	42	64	PROCEDU			
	5-74 15-74	5-2	28-74		70 0		50	%	10 to T	₩ 4F N1	N. F. 14. N.	4 6 14
	IMEN				TEST					TEST RE	SULTS	
NO.	B/W (OHM)	TEST CONFIC.	CAP.	CAP. VOLT. (VOLT)		GAP (IN)	BOOS CLOS TYPE		FUNC. (YES/NO	FUNC.	DENT (IN)	BOOST. FUNC. (YES/ON
63	4.30	c	22	30.0		0.250			YES		0.044	
64	4.44	c	22	30.0		0.250			JEZ	9.4	0.037	
65	4.19	c	22	30.0		0.250			YES	23.0	0.032	
66	4.19	C	22	30.0		0.250			YES	6.9	0.038	
67	4.54	c	22	30.0		0.250			YES	7.3	0.036	
68	4.20	c	22	30.0		0.250			YES	9.1	p. 028	
69	4.31	c	22	30.0		0.250			YES	6.9	0.031	
70	4.23	c	22	30.0		0.250			YES	6.7	4.075	
71	4.52	c	22	30.0		0 250			Yes	8.6	0.033	
						-						
					<u> </u>						Marin.	

- (1) Test Configurations --
 - A Header Assembly Function Time Test (Figure B-1)
 - B Header Assembly "No-fire" Test (Figure B-1)
 C Detonator Dent Output Test (Figure B-2)

 - D Detonator Gap Test (Figure B-3)
 - E Booster (Variable Closure) Initiation Test (Figure B-3)
 - F "Steel Barrier" Test (Figure B-4)
- (2) Bridgewire Resistance After TaH Test
- (3) Broken Lead

TABLE C-3 TEST DATA RECORDS

DEVE	OPMENT				NCTION	SENSIT		1	10314-1			
	SION DE				٠.,	L 7 = 1	t ten	. 264	PROLED I	HE . M	HRAP	APA S.
	START	11 51	COMPLE		V*H , 11	· P (3)		1111111	1 - 1 1	J. 140.01	** F 74 7 *	the tra
	6-74	5-2	28-7		7101		50	%				
SPEC	IMEN	(1)		CAP.	TEST	TEST	BOOS	TER	DE	TOTATOR	SULTS	T -
NO.	B/W (OHM)	TEST CONFIG.	CAP. (UFD)	VOLT.		GAP (IN)	TYPE	THICK.	FUNC. (YES/NO	FILE	DENT (IN)	BOOST. FUNC.
72	4.16	D	22	30.0		0.25	AL	0.005	YES	5.5		No
73	4.00	D	22	30.0		0.10	AL	0.005	YES	7.7		YES
74	4.28	D	22	30.0		0.25	AL	0.005	YES	2.6		No
75	4.28	D	22	30.0	H	0.10	AL	0.005	YES	7.0		YES
76	4.52	D	22	30.0		0.15	AL	0.005	YES	8.1		No
77	4.33	D	22	30.0		0.10	AL	p.005	YES	3.0		YES
78	4.25	D	22	30.0		0.15	AL	0.005	YES	6.5		No
79	4.19	D	22	30.0		0.125	172	0.005	YES	5.8		No
80	4.05	D	22	30.0		0.10	AL	0.005	YES	6.8		YES
18	3.88	D	22	30.0		0.125	AL	0.005	YES	5.2		YES
82	4.55	D	22	30.0		0.15	AL	0.005	YES	22.0		No
83	4.50	D	22	30.0		0.125	AL	0.005	YES	7.4		YES
84	4.47	D	22	30.0		0.15	AL	0.005	YES	8.4		No
85	4.18	D	22	30.0		0.125	AL	0.005	YES	6.7		No
86	4.16	D	22	30.0		0.10	AL	0.005	YES	2.7		YES

NOTES:

- (1) Test Configurations --
 - A Header Assembly Function Time Test (Figure B-1)
 - B Header Assembly "No-fire" Test (Figure B-1)
 - C Detonator Dent Output Test (Figure B-2)

- D Detonator Gap Test (Figure B-3) E Booster (Variable Closure) Initiation Test (Figure B-3)
- F "Steel Barrier" Test (Figure B-4)
- (2) Bridgewire Resistance After T&H Test
- (3) Broken Lead

TABLE C-3
TEST DATA RECORDS

	OPMENT				A WELL	SENSIT		/	10314-1	01	5 (11)	
PREC1	SION DE				NUTTUN	1135/00	1 10	264) H) L D		1 & 4 1	A CA.
	START		COMPLE	. 1	sta ta	'		- 11 -	s = 1	. a [F 1	1 14 1	1 M
	16-74	1 5 -	28-74		7 <i> ° F</i> Tes t		50	10		TOST RE	PIT TO	
NO.	B/W	TEST (1)	CAP.	CAP.	1231	TEST	BOOS CLOS	URE		TONATOR FUNC.	DENT	BOOST.
	(ORM)	CONFIC.	(UFD)	(VOLT)		(IN)	TYPE	THICK.	(YES /NO	(OSEC)	(IN)	(YES/NO
87	4.24	D	22	30.0		0.125	AL	0.005	YES.	6.7		No
88	4.34	D	22	30.0		0.100	AL	0.005	YES	6.0		No
89	3.93	D	22	30.0		0.075	AL	0.005	YES	6.5		YES
90	4.31	D	22	30.0		0.100	AL	0.005	YES	6.7	•	YES
91	4.76	D	22	30.0		0.125	AL	0.005	YES	7.0		ماه
92	4.58	E	22	30.0		0.075	AL	0.016	YES	7.6		YES
93	4.28	E	22	30.0		0.075	AL	0.010	YES	7.0		YES
94	4.36	Ε	22	30.0		0.075	AL	0.010	YE'S	8.1		No
95	4.23	E	22	30.0		0.075	AL	0.010	YES	5.3		YES
96	4.38	E_	22	30.0		0.075	AL	0.010	YES	7.4		YES
97	4.41	E	22	30.0		0.075	S 5	0.010	YE5	6.8		YES
98	4.35	E	22	30.0		0.075	22	0.010	YES	7.0		YES
99	4.36	Ε	22	30.0		0.075	22	0.022	YES	7.4		No
100	4.17	E	22	30.0		0.075	22	0.022	YES	2.4		No

- (1) Test Configurations --
 - A Header Assembly Function Time Test (Figure B-1)
 - B Header Assembly "No-fire" Test (Figure B-1)
 - C Detonator Dent Output Test (Figure B-2)
 - D Detonator Gap Test (Figure B-3)
 - E Booster (Variable Closure) Initiation Test
 - (Figure B-3)
 F "Steel Barrier" Test (Figure B-4)
- (2) Bridgewire Resistance After T&H Test
- (3) Broken Lead

DEVE	LOPMENT			F	DOCTION	" SENS	ITIVITY OUTPUT	:/	10362	MBFH		
PREC		TONATOR	ASS	SY.	OT NO.	101	4	264	PROCEDI	RE NUM	9 f R & P	ARA, NO
	START		COMPL		MB, TE			MIDITY	1151	1 MALILO I	NT NIIV	111111
	3-74 CIMEN	3 -	2 8 -7	4-	70°	7	50	70		TEST RE		
		(1)		CAP.	1531	TES	r BOO	STER	S	SULTS		
NO.	B/W (OHM)	TEST CONFIG.	CAP. (UFD)	VOLT.		GAP (IN	CLO	THICK.	FUNC. (YES/NO	FINC	DENT (IN)	OPEN B/W (YES/N
111	3.98	А	1	5.0					No			No
1/2	4.26	A	1	5.0	<u> </u>	_			No	_		No
113	4.30	A	1	5.0		_			No	-		No
114	4.55	Α	-	5.0					No	-		N.
115	4.25	Α		5.0					No	_		No
116	4.43	Α	1	20.0					No	_		Λ'ρ
/17	4.20	A	1	20.0		<u> </u>			No	_		No.
118	4.18	A	1	20.0					No	_		No
119	4.15	Α	1	20.0	ļ				No	_		No
120	4.31	Α	1	20.0					No			No
121	4.10	Α	1	20.0					No	,		No
122	4.16	Α_	1	20.0		_			ە بىر	-		No
123	4.24	_A	1	20.0					No	-		No
124	4.01	Α	1	20.0					YES	5.4		YES
125	4.29	Ą	1	20.0					No	_		No

- (1) Test Configurations --
 - A Header Assembly Function Time Test (Figure B-1)
 - B Header Assembly "No-fire" Test (Figure B-1)
 - C Detonator Dent Output Test (Figure B-2)
 - D Detonator Gap Test (Figure B-3)
 - E Booster (Variable Closure) Initiation Test (Figure B-3)
 - F "Steel Barrier" Test (Figure B-4)
- (2) Bridgewire Resistance After T&H Test
- (3) Broken Lead 66

TABLE C-3 TEST DATA RECORDS

Sheet 10

DEVE	OPMENT				UNCTION			/	10362			
	NAME MI		HD!	-	OT NO.	l 1 >		264	PROCEDU	RE NIME	SER & P	ARA, NO
	START		CONFILE	TE	ANH, IF	** P. 15			1+51	MAINE	NT NUM	BERM
5-3	-74	5-	28-74	1	700	F	50	%				
SPE	EINEN				TEST	<u>}</u>	-	13 d S		TEST RE	SULTS	
NO.	B/W	TEST CONFIG.	CAP.	VOLT.		GAP		TER SURE THICK.	FUNC.	FUNC.	DENT	OPEN B/W (YES/N
	(OHM)	2/2	(UFD)	(VOL)	'	(IN)	TIFE	(IN)	(YES/NO	(OSEC)	(YN)	(YES/N
126	4.45	Α	1	30.0	<u>, </u>	<u> </u>			YES	220		YES
127	4.20	A		30,0	<u> </u>	ļ			Yes	315		YES
128	4.06	A		30.0	4_				YES	290		YES
129	4.09	Α_	J	30.0	<u>`</u>				No	_		No
130	4.40	A		30.0					YES	390		YES
131	4.46	A	1	30.0					YES	440		YES
132	4.37	_A_	1	30.0				ļ	YES	9.6		YES
133	4.30	A		30.0	<u> </u>			<u> </u>	Y=3	240		YES
134	4.52	A	j	30.0		.	ļ		YEZ	6.8		YES
135	4.36	A	1	30.0			ļ		YES	5.1		YES
136	4.32	A	1	40.0			ļ		YES	11.1		YES
137	4:28	A		40.0	<u> </u>		-	ļ	YES	13.8		Yes
138	4.53	Α,	1	40.	,				YES	12.2		YES
139	4.24	A		40.	0			ļ	YES	12.5		YES
140	4.36	A		40.					YES	13.9		YES

- (1) Test Configurations --
 - A Header Assembly Function Time Test (Figure B-1)
 B Header Assembly "No-fire" Test (Figure B-1)

 - C Detonator Dent Output Test (Figure B-2)
 - D Detonator Gap Test (Figure B-3)
 - E Booster (Variable Closure) Initiation Test
 - (Figure B-3)
 F "Steel Barrier" Test (Figure B-4)
- (2) Bridgewire Resistance After T&H Test
- (3) Broken Lead

TABLE C-3
TEST DATA RECORDS

DEVE	OF TEST				UNCTION			'	10362	ាមម		
PREC	ISION DE	NIATURE TONATOR	/		1 10,	1 OT 91	(CRN	64	PROCEDU	RE SOM	RER & P	ARA, NO
	3-74.	1	28-7		70°F		50		10%1	LUUIPME	NT NUV	HERS
SPE	CIMEN				TEST			News III		TEST RE	SULTS	
NO.	B/W (OHM)	TEST CONFIC.	CAP.	CAP. VOLT. (VOLT)		GAP (IN)	BOOS CLOS TYPE		FIINC	FUNC.	DENT (IN)	OPEN B/W (YES/N
141	4.45	А		40.0					YES	15.4	(5.17)	YES
142	4.43	A		40.0					YES	/3.7		YES
143	4.05	A	1	40.0					YES	10.5		YES
144	4.36	A	1	40.0					453	14.4		YES
145	4.52	Α		40.0					YES	14.1		YES
146	4.45	A	4.7	5.0					No	_		No
147	4.40	A	4.7	5.0					No	_		No
148	4.46	Α	4.7	5.0			785		No	1		No
149	4.47	A	4.7	5.0	,	ļ			No	-		No
150	4.43	Α	4.7	5.0					No	_		No
151	4.56	A	4.7	20.0					Yes	24		YE'S
152	4.30	A	4.1	20.0					YES	21		YEZ
153	4.16	A	4.7	20.0					YES	19		YES
154	3.93	Α	4.7	20.0					YES	18	•	YES
155	4.57	A	4.7	200	,				YES	17		YES

- (1) Test Configurations --
 - A Header Assembly Function Time Test (Figure B-1)
 - B Header Assembly "No-fire" Test (Figure B-1)
 - C Detonator Dent Output Test (Figure B-2)
 - D Detonator Gap Test (Figure B-3)
 - E Booster (Variable Closure) Initiation Test (Figure B-3)
 - F "Steel Barrier" Test (Figure B-4)
- (2) Bridgewire Resistance After T&H Test
- (3) Broken Lead
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TABLE C-3
TEST DATA RECORDS

	OPMENT					SENSIT			10362	CBER		•
	NAME MI		H AS	DR 10	r so.	107 51	. I CHI	64	PHOCEDU	HE NUME	RR& P	ARA, N
	-74 .	5-	COMPLI	1	мн, тт. Со об		L., HUS		1151	au i p M F	NT NUM	HEHS
	IMEN		- 0 -	·	70°F		500	70	T	TOST RE	SULTS	
		TEST (1)		CAP.	**	TEST	BOOS		S	PEC IMEN		OPEN
NO.	B/W (GHM)	CONFIG.	CAP. (LTD)	VOLT.		GAP (IN)	TYPE	титск.	FUNC. (YES/NO	FUNC. TIME (USEC)	DENT (IN)	B/W (YES/
156	4.53	_A_	4.7	20.0					YES	23.5		YES
157	4.54	Α	4.7	20.0	ļ	_			YES	26		YES
158	4.40	A	4.7	20.0					Yes	19.5		YES
159	4.29	Α	4.7	20.0					YES	22.5		YES
160	4.42	Α	4.7	20.0					YES	7		YES
161	4,28	A	4.7	30.0					YES	7.9		YES
162	4.25	A	4.7	30.0					YES	8.2		YES
163	4.23	Α	4.7	30.0					yes	8		YES
164	4.24	_A_	4.7	30.0					YES	8.8		YES
165	4.05	Α	4.7	30.0					YES	7		YES
166	4.35	· A	4.7	30.0			ļ		YES	8.2		YES
167	4.54	A	4.7	30.0					Y63	9.1		YES
168	4.38	A	4.7	30.0					YES	8.8		YES
169	4.49	Α	4.7	30.0					YES	8.4		YES
170	4.41	Δ	4.7	30.0					YEZ	8.5		YES

- (1) Test Configurations --
 - A Header Assembly Function Time Test (Figure B-1)
 - B Header Assembly "No-fire" Test (Figure B-1)
 - C Detonator Dent Output Test (Figure B-2)
 - D Detonator Gap Test (Figure B-3)
 - E Booster (Variable Closure) Initiation Test (Figure B-3)
 - F "Steel Barrier" Test (Figure B-4)
- (2) Bridgewire Resistance After T&H Test
- (3) Broken Lead

TABLE C-3 TEST DATA RECORDS

	LOPMENT			· A	UNCTION	" SENSI	TIVITY	/	10362	-WBFH				
PREC	ISION DE	NIATURE TONATOR	HD ASS	Y.	T NO.	1 117 %	I F C FF	264		IRE NUM	4 & R l R	ARA, SO		
	START		COMPL		AMH, TE		FI., NO		11-57	EQUIPME	NE NUV	BERS		
	3-74.	15-	28-7	4	70°F		50	0/0						
SPE	IMEN	(1)		CAR	TEST	T ====	BOOS	: करा	TEST RESULTS SPECIMEN					
NO.	B/W (OHM)	TEST CONFIC.	CAP.	CAP. VOLT. (VOLT	,	GAP (IN)	CLOS		FUNC.	FUNC.	DENT (IN)	OPEN B/W		
171	4.41	A	4.7	40.0				110	YES	4.2	(411)	YES/N		
172	4.54	A	4.7	40.0	-		<u>'</u>		YES	4.6		YES		
173	4.35	A	4.7	40.0	ļ				YES	4.6		YES		
174	4.50	A	4.7	40.0	ļ				YES	4.8		Y65		
175	4.69	À	4.7	40.0					YES	5.1		Y∈s		
176	4.51	A	4.7	40.0					YES	6.3		YES		
177	4,30	A	4.7	40.0					YES	4.7		YES		
178	4.39	Α	4.7	40.0			ļ		YES	4.6		YES		
179	4.37	_ A	4.7	40.0					Yes	4.8		YES		
180	4.33	A ·	4.7	40.0		<u> </u>			YES	4.7		YES		
181	4.11	<u>A</u>	22	5.0					YES	40.5		YES		
182	4.47	A	22	5.0	-	-	<u> </u>		YES	40.5		YES		
183	4.23	_A	22.	5.0	-	-	ļ		YES	35.0		YES		
184	4.44	_A_	22	5.0			ļ		YES	37.5		YES		
185	4.52	A	22	5.0					YES	41.5	.A.E.	YES		

- (1) Test Configurations --
 - A Header Assembly Function Time Test (Figure B-1)
 - B Header Assembly "No-fire" Test (Figure B-1)
 - C Detonator Dent Output Test (Figure B-2)
 - D Detonator Gap Test (Figure B-3)
 - E Booster (Variable Closure) Initiation Test (Figure B-3)
 - F "Steel Barrier" Test (Figure B-4)
- Bridgewire Resistance After T&H Test Broken Lead 70 (2)
- Broken Lead

TABLE C-3
TEST DATA RECORDS

	OPMENT					SENSI		'	10362	магн		
PRECI	SION DE		HDR ASS	. 1.01	NG110N	11512/01	E CRN		PROCEDU	HE NUME	I.R & P	ARA
	-74		28-74	-	70°	- 1	L. HUA	%	rist !	4MAIDD	NT NUM	BIRS
SPEC	IMEN				TEST		T 8000			TEST RE	SULTS	
NO.	B/W (OHM)	TEST CONFIG.	CAP.	CAP. VOLT. (VOLT)		TEST GAP (IN)	BOOS CLOS		FUNC. (YES/NO	PECIMEN FUNC. TIME	DENT	OPEN B/W
186	4.2.6	Α	22	20.0		(200)		CIND	VES		(IN)	(YES/NO
187	4.49	Α	22	20.0					VES	1.5		Y <i>E</i> \$
188	4.36	Α_	22	20.0		ļ			YES	13.6		YES
189	4.05	Α	22	20.0					YES	12.2		YES
190	4.04	Α_	22	20.0					No	-		YES
191	4.07	A	22	20.0					YES	11.6		YE'S
192	4.02	A	22	20.0					Y∉s	//./		YES
193	4.04	_A_	22	20.0					VES	16.4		YES
194	4.68	_A_	22	20.0			ļ ———		Yes	16.8		YES
195	4.66	A	22	20.0					YES	15.6		YES
	4.32	_A_	22	30.0		 			Y€S	6.0		YE5
	4.22	_A	22	30.0	Š.	+			YES	5.5		\e\c\c\c\c\c\c\c\c\c\c\c\c\c\c\c\c\c\c\
	4.47	A	22	30.0					YE'S	6.4		YES
199 200	4.54	A	22	30.0		-			YES	5.5		YES

- (1) Test Configurations --
 - A Header Assembly Function Time Test (Figure B-1)
 - B Header Assembly "No-fire" Test (Figure B-1)
 - C Detonator Dent Output Test (Figure B-2)
 - D Detonator Gap Test (Figure B-3)
 - E Booster (Variable Closure) Initiation Test (Figure B-3)
 - F "Steel Barrier" Test (Figure B-4)
- (2) Bridgewire Resistance After T&H Test
- (3) Broken Lead

TABLE C-3 TEST DATA RECORDS

DEVE	LOPMENT		7	I	UNCTION	TIME/	OUT	PUT		10362			
	ISION DE		HD	R. SY.	OF NO.	LOT :	1.1		64	PROCEDI) RE N. ME	ER & P	ARA, Su,
	START		COMPL		AMB, TE	MP.	RII		TIDITY	115T	FQUIPME	VT NUV	BIRS
	3-74	5-	28-7	4	70°	F		505	%				
SPEC	IMEN	/:>			TEST			11000	# T T		TEST RE	SULTS	
NO.	B/W (OHM)	TEST CONFIG.	CAP.	CAP. VOLT. (VOLT		TES GAP (IN	-	BOOS CLOS TYPE		FUNC.	FUNC. TIME	DENT (IN)	OPEN B/W (YES/NO
201	4.40	A	22	30.0						YES	5.9		YES
202	4.43	A	22	30.0						YES	6.1		YES
203	4.46	A	22	30.0			_			Y63	7.2		YES
204	4.45	A	22	30.0						Yes	6.7		Y85
205	4.48	A	22	30.0	,					YES	5.9		Y65
206	4.19	A	22	40.0						YES	3.9		VES
207	4.36	Α_	22	40.0						YEZ	3.9		YES
208	4.37	A	22	40.0						YES	4.1		YES
209	4.40	A	22	40.0						YES	3.9		YES
210	4.37	Α	22	40.0						YES	4.0		YES
211	4.37	Α	22	40.0						YES	3.9		YES
212	4.32	A	22	40.0						YES	4.1		YES
213	4.33	A	22	40.0		-	\bot			YES	4.0		YEI
214	4.36	A	22	40.0						YES	4.1		YES
215	4.35	Α	22	40.0						YES	4.1		YES

- (1) Test Configurations --
 - A Header Assembly Function Time Test (Figure B-1)
 - B Header Assembly "No-fire" Test (Figure B-1)
 - C Detonator Dent Output Test (Figure B-2)
 - D Detonator Gap Test (Figure B-3)
 - E Booster (Variable Closure) Initiation Test (Figure B-3)
 - F "Steel Barrier" Test (Figure B-4)
- (2) Bridgewire Resistance After T&H Test
- (3) Broken Lead 72

TABLE C-3
TEST DATA RECORDS

	OPMENT				NCTION I			gA*	10362	STHER		
	SION DET			OR. (O		T 1			PROCEDII	HE W. ME	TR&P	A HA , 10
	START		COMPLE	TI A	MH, FFA1	F'. FF	C = HQ5	HOLFY	T1 = 1 +	GILLE STE	NT NOT	HERM
5-1	3 - 74	5-	13-74		710F		50°	/0				
SPEC	IMEN				TEST		1 8000	Mino		TEST RE	SULTS	
NO.	B/W (OHM)	TEST CONFIG.	CAP. (UFD)	CAP. VOLT. (VOLT)	NO- FIRE (AMP)	TEST GAP (IN)	BOOS CLOS TYPE	URE	FUNC.	FUNC. TIME (USEC)	DENT	OPEN B/W (YES/I
216	4.64	В			0.140				YES			YES
2/7	4.74	В			0.135				YES			YES
218	4.28	В			0.130		ļ		YES			YED
219	3.93	B			0.125				YES			YES
220	4.08	В			0.120				YES			Y∈ 9
221	4.34	В			0.115	<u> </u>			No			No
222	4.22	В			0120				No			الم
223	4.33	B			0.125				YES			YE
224	4.64				0.120	<u> </u>			No			No
235	4.67	В			0.125				YES			ye:
226	4.65	3			0,120	ļ	ļ		No			No
227	4.67	B		<u> </u>	0.125				No			No
228	4.63	3	ļ		0.130				YES			YE
229	4.60	3			0./25	 			YES			YE,
230	4.68	B			0.120				No			No

NOTES:

(1) Test Configurations --

A - Header Assembly Function Time Test (Figure B-1)

B - Header Assembly "No-fire" Test (Figure B-1)

C - Detonator Dent Output Test (Figure B-2)

D - Detonator Gap Test (Figure B-3)

E - Booster (Variable Closure) Initiation Test (Figure B-3)

F - "Steel Barrier" Test (Figure B-4)

(2) Bridgewire Resistance After T&H Test

(3) Broken Lead

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TABLE C-3 TEST DATA RECORDS

	OF TEST				RADITIE				10362	MBER		
ART	OPMENT NAME MIN SION DE		HI	DR. LO	INCTION T	OT SI	FCRN	64	PROCEDU	RE NUME	ERAP	ARA, NO
FF ST	3-74	rest	COMPLE.	TE A	MH, FEMI	P. #6	L. HUN	MIDITY	TF ST F	1M4IUD	NT NUN	BERS
	INEN	13-	13-74		TEST					TEST RES	SULTS	
NO.	B/W (OHM)	TEST CONFIC.	CAP.	CAP. VOLT. (VOLT)	NO- FIRE (AMP)	TEST GAP (IN)	BOOS CLOS TYPE		FUNC. (YES/NO	FUNC.	DENT (IN)	OPEN B/W (YES/:
231	4.72	В			0.125				YES			YES
232	4.74	В			0./20				No			No
233	4.76	В			0.125				YES			YES
234	4.69	В			0.120		ļ		YES			YES
235	4.75	В			0.115				1/2			No
236	4.48	В	J-		0.120				No			No
237	4.45	В			0.125				No			No
238	4.60	В			Q./30				YES			YES
239	4.34	В			0.125		7		No			No
240	4.26	В			0.130				YES			YES
24-1	4.51	B			0.125				No			No
242	4.26	B		سنر	0.130				YES			YES
243	4.24	B			0.125			,	YES			YES
244	4.27	B			0.120				No			No
205	4.48	B			0.125		1		No			No

NOTES: (1) Test Configurations --

A - Header Assembly Function Time Test (Figure B-1)
B - Header Assembly "No-fire" Test (Figure B-1)

C - Detonator Dent Output Test (Figure B-2)

D - Detonator Gap Test (Figure B-3)

E - Booster (Variable Closure) Initiation Test (Figure B-2)

F - "Steel Barrier" Test (Figure B-4)

(2) Header assembly subjected to "no-fire" test

TABLE C-3
TEST DATA RECORDS

DEVEL	OPMENT			FL	NCTION 3				10362	**1 1-12		
PRECI	NA WE MI		HDR ASS	Υ.	1 (v 1		42	64	ात्र मात्र	IHE	a FR A s	A 5 A , 10 1)
5-1	3-74	5-1	3-74		TIOF		50	%	r	11 1		1 1
SPEC	CEN	(1)		CAP.	TOST NO-	mrom	BOOS	T 'R	3*	CEST LE	SULTS	
NO.	B/W (OID)	TEST CONFIG.	CAP, (UFD)	VOLT.	FIRE (AMP)	TEST GAP (IN)	CLOS TYPE		FUNC.	EUNC.	DENT (IN)	GEEN B/T
221	4.43	A	22	30.0	SEE Note 2		10	- 11111	No	(Many)	(111)	YES/NO
222	4.20		22	30.0	SEE NOTE 2			•	No			YES
224	4.62	A	22	30.0	NOTE 2				No		• •	YES
226	4.57	Α	22	30.0	SER NOTE 2				No	-	-	Yes
227	4.71	Α	22	30.0	SEE NOTE 2				No	v	91E -	YES
230	4.62	A	22	30.0	SEE NOT Z	h = 44	NEW .	===	No	Ξ		YE
232	4.76	A	22	30.0	SEE NOTE 2		EL		YES	6.9		YES
235	4.74	-A	22	30.0	SEE 2	- 17	*****	desirability from an a final man	No	villa social		YES
236	4.48	A	22	30.o	SEE NOTE 2			37/45	No			yes.
237	4.42	A	22	30.0	SEC Note 2			E -13.	No	5		YES
239	4.23	A -	22	30.0	SEE NOTE Z			-18	No	100	(bell in	YES
241	4.10	A	22	30.0	SEE NOTE 2		5	2	No			YES
244	4.20	Α	22	30.0	SECT NOTE 2	500	1 1 = 1 -	60% L 10 000 - 1000	No			YES
245	4.26	A	22	30.0	SEE NOTE 2		et.) 14	No		O Marine Make Mar	YES
								dan seri ormigali, siproque	~	Cup rose & days	and, in plants	p. 4

NOTES:

- (1) Test Configurations --
 - A Header Assembly Fe ation Time Test (Figure B-1)
 - B Header Assembly "No-fire" Test (Figure B-1)
 - C Detonator Dent Output Test (Figure B-2)
 - D Detonator Gap Test (Figure B-3)
 - E Booster (Variable Closure) Initiation Test (Figure B-3)
 - F "Steel Barrier" Test (Figure B-4)
- (2) Bridgewire Resistance After T&H Test
- (3) Broken Lead

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TABLE C-3
TEST DATA RECORDS

	OPMENT				METER				10314-			
	NAMI MI	NTATURE			CTION T	OT SIA			PROCEDU		BLA & P.	ARA, NO
	SION DE							64	ENVIRON			
	START	1151	COMPLE	1	H TEST	P, Ri		1110117	11 1	را درا ا	MUN TE	131 10 %
	2-74	5-	28-70	-	70°F		52	%		600 6 05	aux me	
SPEC	DEN	(1)			EST (2)	mr.cm	BOOS	TER	DE'	TOST RE	SULIS	
NO.	B/W (OHM)	TEST CONFIG.	CAP.	CAP. VOLT. (VOLT)	B/W (OHM)	TEST GAP (IN)	CLOS TYPE	THICK.	FUNC. (YES/NO	FUNC. TIME (DS=C)	DENT (IN)	BOOST, FUNC, (YES/NO
301	3.18				3.14				SEE NOTE 3			
	3.02								NOTE 3			
	3.04	c	22	40.0	2.92	0.250			YES	1.4	0.035	
304	4.62	c	22	40.0	4.47	0.250			No			153
305	3.26	2	22	40.0	3.11	0.250			YES	1.4	0.040	
306	2.84	c	22	40.0	2.86	0.250			No			
307	3.18	c	22	40.0	3.09	0.250			No			
308	3.20	<u>e</u>	22	40.0	3.15	0.250			YES	1.5	0.033	
309	3.05							-	SEE NOTE 3		ļ	
310	4.66							ļ	NOTE 3			
311	3.23	c	22	40.0	3.12	0 250			No		-	
312	3.14		·		3.03	ļ		ļ	NOTE 3			
313	3.81		22	40.0	4.62	-		_	No		_	
314	2.96	c	22	40.0	2.87	0.250			No	ļ	-	
315	3.48	1 'c	22	40.0	3.32	0.250			YES	1.4	0 034	

NOTES: (1) Test Configurations --

A - Header Assembly Function Time Test (Figure B-1)

B - Header Assembly "no-fire" Test (Figure B-1)

C - Detonator Dent Output Test (Figure B-2)

D - Detonator Gap Test (Figure B-3)

E - Booster (Variable Closure) Initiation Test (Figure B-3)

F - "Steel Barrier" Test (Figure B-4)

(2) Header assembly subjected to "no-fire" test

TABLE C-3 TEST DATA RECORDS

	OPMENT		·		NCTION I				10314	-103		
PRECI	NA WE MI	TONATOR		101	NO. (011-11	42		ENVIRON	MENT -		A HA , 1
42	2-74		28-7	4	70°F	221	52	%			. T	eg to participate
SPEC	IMEN	713			TEST		BOOS	ተዋዕ	D.	TONATOR	SULTS	
NO.	B/W (OIM)	TEST CONFIG.	CAP. (UFD)	CAP. VOLT. (VOLT)	(2) B/W (OHM)	TEST GAP (IN)	CLOS		FUNC, (YES/NO	FUIC.	DENT (IN)	BOOST. FUNC. (YES/NO
316	3.06	c	22	40.0	2.95	0:250			YET		0 043	17.37 310
317	2.92	c	22	40.0	2.80	0.250			YES	1.6	0.032	
318	3.50				3,33				NOTE 4			
319	3.26	c	22	40.0	3.16	0.250			YES	1.4	0 040	
320	2.77	c	22	40.0	2.73	0 250			YES	1.5	0.041	
321	2.71	F	22	40.0	2.60	0100			YES	1.3	SEE NO	78 (3)
322	2.98	F	22	40.0	2.89	0.100			YES	1.4	SEE NO	76(3)
323	3.18	F	22	40.0	3.06	0.100			YES	1.3	SEE NO	TE (3)
324	3.12				2.90				NOTE 4			
325	3.40		22	40.0	3.28				No			
326	4.14				3.84				NOTE 4			
327	3.74	C	22	40.0	3.63	0.250			No			
328	3.45	F	22	40.0	3.61	0 100			YES	1.6	SEE NO	TE (3)
329	3:09				4.40				NOTE 4			
330	3.89	C	22	40.0	4.01	0.250			No			

Notes: (1) Test Configurations --

A - Header Assembly Function Time Test (Figure B-1)

B - Header Assembly "No-fire" Test (Figure B-1)
C - Detonator Dent Output Test (Figure B-2)

D - Detonator Gap Test (Figure B-3)

E - Booster (Variable Closure) Initiation Test (Figure B-3)

F - "Stee. Barrier" Test (Figure B-4)

Bridgewire Resistance After T&H Test

Barrier penetration: 1st - hole; 2d - partial; 3d - dent (3) 4th - none

(4) Broken lead

TABLE C-3 TEST DATA RECORDS

DEVEL	OPMENT			FU	NCTION	TIME/OU	TPUT		10314	-103		
PRECI	SION DE	TONATOR			1 ·		42	64	ENVIRON	MENT - 1	r&H	
	2-74	5-	28-7	4	70°/		52		1151	F (4) (1) (4) (1)	Talif Talia Mi	lii+ kp
SPEC	IMEN				TEST				T	12ST PE	SULTS	
NO.	B/W	TEST CONFIG.	CAP.	CAP. VOLT.	(2) B/W	GAP	BOOS CLOS	URE	FUNC.	FUNC.	DENT	BOOST.
	(OHM)	dom 10.	(UFD)	(VOLT)	(OHM)	(IN)	TYPE	THICK.	(YES/NO	Tosecy	(IN)	(YES/N
331	3,10	F	22	40,0	3.12				No			
332	4.05	F	22	40.0	4.11	0.100			YES	1.4	SEE NO	rs (3)
						 						
					-1							
						1						

NOTES: (1) Test Configurations --

A - Header Assembly Function Time Test (Figure B-1)

B - Header Assembly "No-fire" Test (Figure B-1)

C - Detonator Dent Output Test (Figure B-2)

D - Detonator Gap Test (Figure B-3)

E - Booster (Variable Closure) Initiation Test

(Figure B-3)

F - "Steel Barrier" Test (Figure B-4)

Bridgewire Resistance After T&H Test (2)

Barrier penetration: 1st - hole; 2d - partial; 3d - dent (3) 4th - none

TABLE C-3
TEST DATA RECORDS

	OPMENT				NCTION	SENSIT			10314-			
	SION DE					. T =1	E FEE	64	ENVIRON			ARA: "
TLST:		1	COMPL		он, г е (1	P. 12:		710115	1147	GILLE	NINIM	HERS
	2.74	5-2	28-74		70 °F		52 %	0				
SPEC	IMEN	(3)		CAP.	TEST	TEST	BOOS	TER	DE	TEST RE	SULTS	Γ
NO.	B/W (OHM)	TEST CONFIG.		VOLT.	B/W (OHM)	GAP (IN)	CLOS TYPE	THICK.	FUNC. (YES/NO	FUNC.	DENT (IN)	BOOST. FUNC. (YES/N
333	3.12	c	22	40.0	3.20	0.250			No			
334	2.88	c	22	40.0	2.91	0.250			YES	1.3	0.037	
335	2.90	2	22	40.0	2.96	0.250			No			
336	3.99	C	22	40.0	4.08	0.250			No			
337	3.59	c	22	40.0	3.69	0.250			YES	1.3	0.042	
338	4.20	c	22	40.0	4.64	0.250			No			
339	3.26	<u>c</u>	22	40.0	3.33	0.250			No			
<u>340</u>	3.04	_ د	22	40.0	3.12	0.250	· · · · · · · · · · · · · · · · · · ·		No			
341	3.11	c	22	40.0	3.24	0.250			No			
342	3.19	c	22	40,0	3.30	0.250			No			
343	3.26	0	22	40.0	3.32	0.250			No			
344	3.64	c	22	40.0	3.75	0.250			YES	1.6	0.034	
345	2.90	_c_	22	40.0	2.96	0.250			No			
346	3.27	c	22	40.0	3.40	0.250			No			
347	2.84	c	22	40.0	2.90	0.250	٠.		Y∉s	1.4	0.036	

- (1) Test Configurations --
 - A Header Assembly Function Time Test (Figure B-1)
 - B Header Assembly "No-fire" Test (Figure B-1)
 - C Detonator Dent Output Test (Figure B-2)
 - D Detonator Gap Test (Figure B-3)
 - E Booster (Variable Closure) Initiation Test (Figure B-3)
 - F "Steel Barrier" Test (Figure B-4)
- (2) Bridgewire Resistance After 15,000-g shock
- (3) Broken Lead

TABLE C-3 TEST DATA RECORDS

	OPMENT			- 1	EUNCTION		TIVITY	T_{-}	10314-	103		
PRECI	SION DE	TONATOR		1	11 1-11.	7 1	C 19	264	120 1 1 12 1	HE '	15:1 R & P	A HA -
	15-74		28-74		7001		50	0/0		- an () 11	to To Neg to	1,1 4
SPEC	THEN				TEST					TOST R	ESULTS	
NO.	B/W	TEST CONFIC.	CAP.	CAP.		TEST CAP		STER SURE	FUNC.	TONATO	DENT	BOOST.
	(OHM)		(UFD)	(VOLT	(1)	(IN)	TAPE	THICK.	(YES/NO	tosta	(IN)	(YES/N
348	2.79	e	22	40.0		0.250	ļ		YES	1.5	0.030	
349	3.16	c	22	40.0	,	0.250			YES	1.4	0.034	
350	3.50.	C	22	40.0		0.250			No			
351	2.72	c	22	40.0	<u> </u>	().250			YES	1.4	0,032	
352	4.17	c	22	40.0		0.250			YES	1.3	0,033	
353	4.29	c	22	40.0	,	0.256			YES	/. 3	0.03/	
354	4.28	c	22	40.0	0	0.250			YES	1.5	0.046	
355	3.22	c	22	40.0		0.250			YES	1.5	0.041	
356	4.43	C	22	40.0	5	0.250			No			
357	4.34	e	22	40.0		0.250			Y65	1.4	0.034	
358	3.09	<u>c</u>	22	40.0		0.250			YES	1.5	0.035	
359	3.44	c	22	40.0		0.250			YES	1.4	0.032	
360	2.98	2	22	40.0	<u> </u>	0,250			YES	1.3	0.037	
361	3.42	c	22	40.0		0.250			No			
362	3.22	c	22	40.	ه	0.250			YES	1.3	0.030	

NOTES: (1) Test Configurations --

A - Header Assembly Function Time Test (Figure B-1)
B - Header Assembly "No-fire" Test (Figure B-1)
C - Detonator Dent Output Test (Figure B-2)
D - Detonator Gap Test (Figure B-3)

E - Booster (Variable Closure) Initiation Test

(Figure B-3)
F - "Steel Barrier" Test (Figure B-4)

TABLE C-3 TEST DATA RECORDS

	OTHERNIE					SENSIT		/		MILL H		
	OPPENT	NE A MICES			NCTION	TIME/OU	TPUT		10314-		1.0.0	ARA NO.
	SION DE			112,			4	264	5 4 () (E D)	ME / WI	ITH & I-	A 14 A
TIST		1151	• -	· A	111 - 11	V181 121		11	- 1	- 196 m		-0
5-1	15-74	5-2	28-7	4	700	F	50	%				
SPEC	IMEN				TEST	·				TEST RE	SULTS	
NO.	B/W (OHM)	TEST CONFIG.	CAP.	CAP. VOLT. (VOLT)		TEST GAP (IN)		STER SURE THICK.	FUNC. (YES/NO	FUNC.	DENT (IN)	BOOST. FUNC.
363	2.77	E	22	40.0		0.075	AL	0,020	YES	1.2		YES
364	3.00	Ε	22	40.0		0.075	AL	0.025	YES	1.2		No
365	3.32	Ε	22	40.0		0.075	AL	0.025	YES	1.2		No
366	3.80	6	22	40.0		0.075	AL	0.020	YES	1.3		YES
367	3.86	E	22	40.0	<u> </u>	0.075	AL	0.020	YES	1.3		No
368	3.65	E	22	40.0		0.075	AL	0.020	YES	1.2		155
369	3.65	Ε	22	40.0	ļ	0.075	AL	0.020	YES	1.2		No
370	3.25	E	22	40.0		0.075	AL	0.020	YES	1.3		No
37/	3.36	E	22	40.0		0.075	AL	0.020	YES	1.3		YES
372	3.52	E	22	40.0		0.075	AL	0.016	YES	1.3		YES
373	3.09	E	22	40.0		0.075	AL	0.016	YE.Z	1.3		No
374	3.68	E	22	40.0		0.075	AL	0.016	YES	1.4		YES
375	3.64	E	22	40.0		0.075	AL	0.016	YES	1.5		No
376	2.84	Ε	22	40.0		0.075	AL	0.016	YES	1.4		No
377	2.83	Ε	22	40.0	<u></u>	0.075	AL	0.016	YES	1.3		YES

Notes: (1) Test Configurations --

A - Header Assembly Function Time Test (Figure B-1)

B - Header Assembly "No-fire" Test (Figure B-1)
C - Detonator Dent Output Test (Figure B-2)

D - Detonator Gap Test (Figure B-3)

E - Booster (Variable Closure) Initiation Test

(Figure B-3)

TABLE C-3 TEST DATA RECORDS

	OPMENT					SENSIT			10314-	103		
PATT	SION DE			FUN		TIME/OU	1	264	9 ROLL D.		1 8 8 4 6	ATA
5-1	5-74		8-74	1	700	<u> </u>	500	%		- 1	*, * *, *	
SPEC				1	TEST				C Table	TTOT RE	SULTS	
NO.	B/W (OHM)	TEST CONFIC.	CAP.	CAP. VOLT. (VOLT)		TEST GAP (IN)	BOOS CLOS TYPE		FUNC. (YES/NO	FUNC.	DENT (IN)	BOOST, FUNC. (YG3/N
378	3.88	Ε	22	40.0		0.075	55	0.005	YES	1.2		YES
379	4,00	E	22	40.0		0.075	ss	0010	YES	1.2		YES
380	3.31	E	12	40.0		0.075	35	0.015	YES	1.3		YES
381	2.77	E.	22	40.0		0,075	SS	0.022	YES	1.3		No
382	3.38	E	22	40.0		0.075	SS	0.015	YES	1.2		YES
383	4.36	E	22	40.0		0.075	SS	0.015	YES	1.2		YES
384	3.73	E	22	40.0		0.075	55	0.015	YES	1.1		No
385	298	E	22	40.0		0.075	S.S.	2015	YES	1.3		No
386	4.12	E	22	400		0.075	SS	0.015	YES	1.2		No
387	4.47	E	2.2	40.0		0.075	<u> 55</u>	0.015	YES	1.2		No
388	4.31	E	22	40.0		0.075	55	0.015	YES	1.1		YES
389	3.57	E	22	40.0		0.075	SS	0.010	YES	1.4		YES
390	3.45	E	22	40.0		0.075	22	0010	YES	/. 3		465
39!	3.21	E	22	40.0		0.075	22	0.010	YES	1.3		YES
392	3.19	E	22	40.0		0.075	22	0.010	YES	1.3		YES

NOTES: (1) Test Configurations --

A - Header Assembly Function Time Test (Figure B-1)
B - Header Assembly "No-fire" Test (Figure B-1)
C - Detonator Dent Output Test (Figure B-2)

D - Detonator Gap Test (Figure B-3)

E - Booster (Variable Closure) Initiation Test

(Figure B-3)

TABLE C-3 TEST DATA RECORDS

	OPTENT			F	UNICTION	SENSIT	IVITY,	1	10314-1			
PRECI	SION DE				· T - 'S O ,	1 1 7 1 1		264	DISOV F.D.	IRE S TO	HAI	ALA
	5-74		28-7		70 %		50	0/	114.	Година	NT NO.	•нін-
SPEC					TEST			4		TEST RE	SULTS	
NO.	B/W (OHM)	TEST CONFIG.	CAP. (UFD)	CAP. VOLT. (VOLT		TEST GAP (IN)	EOOS CLOS TYPE		FUNC.	FUNC. TIME (USEC)	DENT (IN)	BOOST, FUNC. (YES/N
393	4.24	F	22	40.0		0.100			YES	/.3		
394	3.49	F	22	40.0		0.100			No			
395	3.04	F.	22	40.0		0,/00			No			
396	3.49	F	22	40.0	rees to	0.100			YES	1.5		
397	3.04	F	22	40.0		0./00			YES	1.5		
398	3.35	F	22	40.0		0.100			No			
399	3.99	F	22	40.0	,	0.100			YES	1.4		
400	3.57	F	22	40.0		0.100			No			
401	2.82	F	22	40.0		0.100			YES	1.4		
402	3.89	F	22	40.0		0,100			No			

NOTES: (1) Test Configurations --

A - Header Assembly Function Time Test (Figure B-1)

B - Header Assembly 'No-fire' Test (Figure B-1)
C - Detonator Dent Output Test (Figure B-2)

D - Detonator Gap Test (Figure B-3)

E - Booster (Variable Closure) Initiation Test

(Figure B-3)

TABLE C-3 TEST DATA RECORDS

DEVE	OF LEST			F	UNCTION	TIME/	UTP	UT		10507			
PRECI		TONATOR,		SY.	OT NO.	LITS		42	64	ркоскои	RE NUME	ERAP	ARA, NO.
	START		COMPL	1	AMB, TE				1 ID LTV	TEST	QUIPME	NT NUN	BERS
	3 - 74	3-4	28-7	4	7001			50	10	W	mnam to		
SPEC	LIEN	(1)		CAP.	TEST	TEST		BOOS	TER	S	TEST RE	SULTS	
NO.	B/W (OHM)	TEST CONFIC.	CAP. (UFD)	VOLT.)	GAP (IN)		CLOS YPE	THICK.	FUNC. (YES/NO	FINC	DENT (IN)	OPEN B/W (YES/NO
411	3.89	A	1	5.0						No			No
412	4.15	A	1	5.0						N.	-		No
413	3.93	A	1	5.0			_			No			No
414	4,04	A	1	5.0						No	-		No
415	4.24	A	1	5.0						No	-		No
416	3.67	Α		10.0						No	1		YES
417	4.27	A		10.0						No		4	YES
418	4.60	A	1	10.0						No	_	,	YES
419	4.34	A	1	10.0			1			No	_		YES
420	4.31	A	1	10.0			_			No	_		Y65
421	3.91	A		20.0			_			No	-		y65
422	3.97	_A_	1	20.0			1	!		No	-		V€s
423	3.56	Α	1_1_	20.0						No	-		YES
424	3.66	Α	1	20.0			_			No	-		YES
425	3.65	А	1	20.0						No	-		YES

- (1) Test Configurations --
 - A Header Assembly Function Time Test (Figure B-1)
 - B Header Assembly "No-fire" Test (Figure 3-1)
 - C Detonator Dent Output Test (Figure B-2)
 - D Detonator Gap Test (Figure B-3)
 - E Booster (Variable Closure) Initiation Test F "Steel Barrier" Test (Figure B-4)

TABLE C-3 TEST DATA RECORDS

DEVEL	OPMENT		7715	F	UNCTION	SENSI'	UTPUT		10507			
		NIATURE TONATOR	ASS)T NU.	101 -1		264	PROCEDI	HE NUME	SER & P	APA THE
	START		COMPLE		AMB, IE	MP. R	tt, Hu		7 1 - 1	FOULPME	NT NOW	BERS
	3-74	5-	28-7	4	70°F		50	%				
SPEC	IMEN	(1)		CAP.	TEST	TEST	BOOS	TER	SP	TEST RE	SULTS	
NO.	B/W (OHM)	TEST CONFIG.	CAP. (UFD)	VOLT.)	GAP (IN)	TYPE	THICK.	FUNC.	FUNC. TIME (DSEC)	DENT (IN)	OPEN B/W (YES/)
426	4.63	Α		20.0					No	_	,	YES
427	3.54	A		20.0					No			YES
428	4.12	A_	1	20.0	-				No	_		YES
429	3.96	A		20.0				174	No			YES
430	3.68	_A	1	20.0					No	~		YES
431	4.36	Α	1	30.0					YES	0.7		IES
432	3.79	Α	1	30.0					No	_	-	YES
433	4.44	Α_	1	30.0	ļ				YES	0.5		YES
434	4.59	A		30.0					No	_		YES
435	3.30	Α	1	30.0	-				YES	0.6		YES
436	3.29	Α	!	30.0					YES	0.7		YE5
437	3.44	Α	1	30.0	-		İ		YE5	0.9		YES
438	3.58	A	1	30.0					No			YES
439	3.62	A	1	30.0	-				No			YES
4.10	3.61	А		30.0					No	j. 		YES

Notes: (1) Test Configurations --

A - Header Assembly Function Time Test (Figure B-1)
B - Header Assembly "No-fire" Test (Figure B-1)
C - Detonator Dent Output Test (Figure B-2)

D - Detonator Gap Test (Figure B-3) E - Booster (Variable Closure) Initiation Test

(Figure B-3)

TABLE C-3
TEST DATA RECORDS

DEVEL	OPMENT			F	UNCTION					10507	MBER		
PRECI	SION DE	TONATOR	ASS	SY.	OT NO.	L 1) T - s			64	PROCEDU		. •	
5-3.			COMPLE 28-74		70° F			09	LIDITY	11-11	GUIPUE	AT NOW	HF RS
SPEC			20 /7		TEST			0 /	0	- 1/	TEST RE	SULTS	
NO.	B/W	TEST CONFIG.	CAP.	CAP.		TEST GAP		BOOS CLOS YPE	URE	FUNC.	FUNC.	DENT	OPEN B/W
	(OHM)		(UFD)	(VOLI)	(IN)	- 1	IPE	THICK.	(YES/NO	(dsec)	(IN)	(YES/N
441	4.09	A		30.0			1			No			YES
442	4.13	A	ı	30.0			1			YES	0.6	61.1.1	YES
443	3.74	Α	1	30.0						YES	0.7		YES
444	3.44	A	1	30.0			\perp			YES	0.6		YES
445	4.32	A	1	30.0						No	~		YES
446	3.69	Α	1	30.0						No	- 4	,	Y€S
447	3.73	Α		30.0						No			YES
448	3.68	A		30.0			\perp			YES	0.7		YES
449	4.19	A	1	30.0						No	-	7 *	Y∈s
450	3.73	А	1	30.	,					YES	0.6	3 4117	Y€S
451	3.62	A	1	40.0	,					YES	0.9		YES
452	3.96	A	1	40.0						No			YES
453	3.63	A	1	40.0			_			No			YES
454	3.40	Α		40.0	,					YES	0.5		YES
455	3.15	A		40.0						YES	0.5		YES

NOTES: (1) Test Configurations --

A - Header Assembly Function Time Test (Figure B-1)

B - Header Assembly "No-fire" Test (Figure B-1)

C - Detonator Dent Output Test (Figure B-2)

D - Detonator Gap Test (Figure B-3)

E - Booster (Variable Closure) Initation Test (Figure B-5)

TABLE C-3 TEST DATA RECORDS

DEVEL	OF TEST				UNCTION					10507		ST RESULTS STRESULTS SIMEN OPE NY SEC) (IN) (YES 4 YE 4 YE 5 YE 4 YE 5 YE 4 YE 5 YE 7 YE			
	NAME MI		HDF		OT NO.	1 O T	*1 . t	42		PROCEDU	RE NUMB	ER & P.	ARA. NO		
PRECI	SION DE		ASS		AMH, IE	MP.	RF L		11DITY	TEST	GUIPME	NT NUM	BERS		
5-3	-74	5-2	28-74	4	700F	-		50°	10						
	IMEN				TEST			BOOS			TEST RES	SULTS			
NO.	B/W (OHM)	TEST CONFIG.	CAP.	VOLT.		GAI	P	CLOS TYPE		FUNC. (YES/NO	FUNC.		OPEN B/W (YES/N		
456	4.75	R	1	40.	0					YES	0.5		YES		
451	4.69	A	1	40.0						YES	0.5		YES		
458	4.88	A		40.0						X∈S	0.4		YES		
459	4.64	Α	1	40.0	<u> </u>					VES	0.4		YES		
460	4.23	٨	1	40.	0					YES	0.4		YES		
461	3.64	A_	1	40.	0					Y65	0.5		157		
462	3.67	Α		40.	0					YES	0.4		YES		
463	3.61	A	1	40.	0					No	_		YES		
464	3.54	A	1	40.	0					YES	0.5		YES		
465	3.27	A		40.	0					YES	0.4		YES		
466	3.15	Α	1	40.	<u>, </u>					YES	0.4		YET		
467	4.33	A	. 1	40.	0					YES	0.5		YES		
468	4.34	A	1	40.	0		_			YES	0.5		YES		
469	3.93	A		40.	0					YES	9.4		YES		
410	4.72	A		40.	0					YES	0,5		YES		

NOTES: (1) Test Configurations --

A - Header Assembly Function Time Test (Figure B-1)
B - Header Assembly "No-fire" Test (Figure B-1)

C - Detonator Dent Output Test (Figure B-2)

D - Detonator Gap Test (Figure B-3)

E - Booster (Variable Closure) Initiation Test

(Figure B-3) F - 'Steel Barrier" Test (Figure B-4)

TABLE C-3 TEST DATA RECORDS

	OF TEST				FUNCTION				10507	мвін		
	SION DE	NIATURE TONATOR	ASS	OR.		101 51	1 120	264	PHOLIDII	RE NI ME	FR&P	ARA, 10
TEST :	-74 ·	1	COMPLI 28-74		AMB, TE		- L 111/1		1141	FQUIPME	NT NUM	HIRS
SPEC		1 3 - 4	.8-/-	7	70°F		509	٥		TEST RE	פת חופ	
	A HALL	TEST (1)		CAP.		TEST	BOOS			SPECIMEN		
NO.	B/W (OHM)	CONFIG.	CAP. (UPD)	VOLT		GAP (IN)	TYPE	THICK.	FUNC. (YES/NO	FUNC. TIME (USEC)	DENT (IN)	OPEN B/W (YES/N
471	4.13	A	4.7	5.0					No	_		YES
472	3.88	Α	4.7	5.0					No			YES
473	3.98	_A_	4.7	5.0					No	_		YES
474	4.58	Α	4.7	5.0				ed in e	No			YES
475	3.9.2	A	4.7	5.0					No	_		YES
476	3.65	A	4.7	10.	,				No	_		YES
477	2.97	A	4.7	10.0					No	_		Y65
418	2.96	A	4.7	10.0	>				No			Y55
419	4.01	A	4.7	10.0	<u>, </u>				No			YES
480	3.38	A	4.7	10.0					No	·-		465
481	3.50	Α_	4.7	20.					No			YES
482	3.38	Α_	4.7	20.0	2				YES	0.8		YES
483	3.33	Α	4.7	20.0		-			No			YES
484	3.13	Α	4.7	20.0	>				YES	0.9		YES
485	3.22	A	4.7	20.0					No	-		YES

NOTES:

(1) Test Configurations -A - Header Assembly Function Time Test (Figure B-1)
B - Header Assembly "No-fire" Test (Figure B-1)
C - Detonator Dent Output Test (Figure B-2)

D - Detonator Gap Test (Figure B-3)

E - Booster (Variable Closure) Initiation Test

(Figure B-3)

TABLE C-3 TEST DATA RECORDS

DEVE	LOPMENT			,	FUNCTION	SENSI	TIVITY,	/	10507	MBER		
PREC	IS ION DE	NIATURE TONATOR	/ AS	SSY.	LOT NO.	LUT SI	El CR	264		URE NIM	BER & F	ARA. NO
	5-74		28-7		70°F		50		fret	FUUIPME	NT NUN	18185
	IMEN				TEST					TEST RE	SILTS	
NO.	B/W (OHM)	TEST CONFIC.	CAP.	VOLT (VOL		CAP	BOOS CLOS	URE	FUNC.	FUNC.	DENT	OPEN P/U
486	3.43	A	4.7	20.0		(IN)	11116	тыіск.	(YES/NO	WEEL -	(IN)	B/W CYES/N
487	3.16	A	4.7	20.					YES	1.0		YES
488	4.88	Α	4.7	20.0	0				No		Ad b	YEZ XEZ
489	4.89	Α	4.7	20.0	,				No	_		YES
490	4.47	_A_	4.7	20.0	,				No	_		Y€s
491	4.48	A	4.7	30.	0				YES	0.5		YE"
492	4.54	Α	4.7	30.0	e				No			YES
493	4.44	Α	4.7	30.0	0	ļ			No			YES
494	4.34	Α	4.7	30.0	>				YES	0.6		YES
495	4.81	_A	4.7	30.0		-			No	_		YES
196	3.31	A	4.7	30.0					YES	0,6		YES
197	3.90	A	4.7	30.0						0.5		YES
498 499	4.92	A	4.7	30.0					No	_		YES
500	3.31	A	4.7	30.0						0.7		YES YES

- (1) Test Configurations --
 - A Header Assembly Function Time Test (Figure B-1)
 B Header Assembly "No-fire" Test (Figure B-1)

 - C Detonator Dent Output Test (Figure B-2)
 - D Detonator Gap Test (Figure B-3)
 - E Booster (Variable Closure) Initiation Test
 - F "Steel Barrier" Test (Figure B-4)

TABLE C-3 TEST DATA RECORDS

	OPMENT				AMETER				10507	MBLR		
PART	NAME MI	NIATURE TONATOR	HD	R. 10	INCTION T	1 17 51	I CAN	264		IRE NUME	FRAP	ARA, NO
TEST :		_	COMPL		MB. TEN	P. RI	1 HU!		1157	FQUIPME	NT NUM	BERS
5-3		5-2	8-74	7	70°F		50	%		TEST RE	CITY TO	
SPEC	IMEN	(1)		CAP.	1431	TEST	BOOS		S	PECIMEN	30613	
NO.	B/W (OHM)	TEST CONFIG.	CAP. (UPD)	VOLT.		GAP (IN)	TYPE	THICK.	FUNC. (YES/NO	FUNC. TIME. (DSEC)	DENT (IN)	OPEN B/W (YES/N
501	4.14	A	4.7	30.0	ļ				YES	0.6		YES
502	3.97	A	4.7	30.0					YES	0.7		YES
503	4.65	A	4.7	30.0		<u> </u>			YES	0.6		YES
504	3.55	Α	4.7	30.0	ļ				YES	0.6		YES
505	3.68	A	4.7	30.0					YES	0.5		YEZ
506	3.79	Α	4.7	30.0					YES	0.6		YES
507	4.12	A	4.7	30.0					No			YES
508	4.26	A	4.7	30.0					No	_		YES
509	4.78	A	4.7	30.0					YES	0.7		VES
510	3.76	A	4.7	30,0					YES	0.5		YES
511	4.56	A	4.7	40.0			ļ		YES	0.65		YES
512	4.32	A	4.7	40.0				ļ	YES	0.5		YES
513	3.51	Α	4.7	40.0	>				YES	0.6		YES
514	3.91	Α	4.7	40.0					No			YES
515	3.66	A	4.7	40.0					YES	0.5		YES

Notes: (1) Test Configurations --

A - Header Assembly Function Time Test (Figure B-1)

B - Header Assembly "No-fire" Test (Figure B-1) C - Detonator Dent Output Test (Figure B-2)

D - Detonator Gap Test (Figure B-3)

E - Booster (Variable Closure) Initiation Test

(Figure B-3)

TABLE C-3
TEST DATA RECORDS

	PMENT				CTION TI		IVITY/ TPUT		10507		T RESULTS IMEN NC. DENT B/W SEC) (IN) (YES/N AS YES S YES S YES YES YES YES YES			
ART	SION DET	CONATOR	HDR	Y. + 31	NO. 111	1	42	339						
7 ST S		100000000000000000000000000000000000000	8-74		70°F		50%	6		ASTA NOT				
SPEC		-	.0 /-		TEST		BOOS	TED	S	PECIMEN	SULTS			
NO.	B/W (OHM)	TEST CONFIG.	CAP.	CAP. VOLT. (VOLT)		rest Gap (IN)	CLOS	THICK.	FUNC. (YES/NO	FUNC.	PERMIT	B/W		
516	3./8	Α	4.7	40.0					YES	0.45		YES		
517	3.58	Α	4.7	40.0					YES	0.5		X=2		
518	3.14	Α	4.7	40.0					y€3	0.5	W. 1	Yes		
519	2.90	Α	4.7	40.0					YES	0.5	17	YES		
520	2.91	A	4.7	40.0					Yes	0.5		YES		
520 521	2.95		4.7	40.0					YES	0.6		YES.		
522	3.41	A	4.7	40.0					YES	0,55		YES		
523		A	4.1	40.0				1	YES	0.6	-	YF		
524		A	4.7	40.0					YES	0.6	1	YES		
525	1	A	4.2	40.0					YES	0.5		YES		
524	3.25		4.7	40.0				100	YES	0.55		YES		
527		1 .	4.1	40.0			_	- 54	YES	0.5	1	YES		
528		A	4.7	40.0				0,7	YES	0.55		Yes		
529		A	4.1	40.0					YES	0.5		YE		
530		1	47	40.0				1004	YES	0.45		YES		

NOTES: (1) Test Configurations --

A - Header Assembly Function Time Test (Figure B-1)

B - Header Assembly "No-fire" Test (Figure B-1)

C - Detonator Dent Output Test (Figure B-2)

D - Detonator Gap Test (Figure B-3)

E - Booster (Variable Closure) Initiation Test

(Figure B-3)

TABLE C-3
TEST DATA RECORDS

DEVE	OPMENT			12	FUNCTION	SENSI	TIVITY	1	10507	мигн		
PRECI	ISION DE	NLATURE TONATOR	AS	SY.	OT NO,	LOTS	LLEH	264	PHOLLDU	RE NUM	BIRAP	ARA. S
5-3	3-74		COMPL 28-74		700F		50		IIST	EQUIPME	NE NUM	18185
SPEC	IMEN	7.			TEST					TEST RE	SULTS	
NO.	B/W (OHM)	TEST CONFIG.	CAP.	VOLT (VOL		GAP (IN)	BOOS CLOS TYPE		FUNC. (YES/NO	FUNC.	DENT (IN)	OPEN B/W
531	3.64	A	22	5.0					No		(4117)	YES/
532	3.38	A	22	5.0					No	1		YES
533	3.58	A	22	5.0					No			VE
534	2.76	A	22	5.0					No	_		YET
535	3.09	A	22	5.0)				No			YES
536	2.64	_A_	22	10.	0				No	_		YES
537	2.82	Δ	22	10.0	,				Nu	_		YES
53 <i>B</i>	2.91	Δ,	22	10.0	,				No	_		YES
539	2.79	Α	22	10.0)				No			YES
540	2.90	À	22	10.0					No	_		YES
241	4.49	_A	22	20.0	,				No			YES
542	3.04	_A	22	20.0)				No			YES
43	3.09	Α	22	20.0		-			No	_		YES
44	2.97	<u>A</u>	22	20.0	,	ļ			No	-		YES
545	3.17	A	22	20.0					No	_	0.1	YES

NOTES: (1) Test Configurations --

A - Header Assembly Function Time Test (Figure B-1)

B - Header Assembly "No-fire" Test (Figure B-1)

C - Detonator Dent Output Test (Figure B-2)

D - Detonator Gap Test (Figure B-3)

E - Booste: (Variable Closure) Initiation Test

(Figure B-3)

TAbLE C-3 TEST DATA RECORDS

DEVEL	OF TEST				FUNCTION				10507	·VBF H		
PRECI	NAMI MI ISION DE	TONATOR	AS	SY.	LOT NO.	107 51	42	64	PPOCEDI	JRE N. N.F	FRAP	A PA
	3-74		28-74		740 F	. P. ⊞		oloits .	1 - 1	14111	NI NOM	INT PES
	IMEN	13-2	-6-14		70°F TEST		200	/0	T	TEST RE	ein Te	
NO.	B/W	TEST (1)	GAR	CAP		TEST	BOOS			PECIMEN		OPEN
NO.	(OHM)	CONFIG.	CAP. (UFD)	VOLT (VOL		GAP (IN)	TYPE	тијск.	FUNC. (YES/NO	FUNC. TIME (DSEC)	DENT (IN)	B/W CYES/S
546	3.00	A	22	20.	0				No	_		YES
547	2.82	A	22	20.	0				YES	0.7		YES
548	3.06	A	22	20.	0	ļ			YES	0.8		YES
549	3.18	Α	22	20.	0				YES	1.0		YES
<u>550</u>	3.22	Α	22	20.	0	ļ			YES	0.9		YES
551	2.76	A	22	30.	0				YES	0.6		YES
552	3.21	Α	22	30.0	,	ļ			No			YES
523	3.01	Α	22	30.	0				YES	0.6		YES
554	3.47	Α	22	30.0	,				Yes	0.6		Y€2
555	2.35	_A	22	30.0	0				YES	0.5		YES
556	3.76	A	22	30.0	0				YES	0.6		Y= s
557	3:51	A	22	30.	0	-			YES	0,5		Y∈5
558	4.21	Α	22	30.	0				No			YES
569	3.45	Α	22	30.	0				No			Y≧s
560	3.84	A	22	30.0	0				YES	0.6		YES

NOTES: (1) Test Configurations --

A - Header Assembly Function Time Test (Figure B-1)
B - Header Assembly "No-fire" Test (Figure B-1)
C - Detonator Dent Output Test (Figure B-2)

D - Detenator Gap Test (Figure B-3)

E - Booster (Variable Closure) Initiation Test (Figure B-3)

TABLE C-3 TEST DATA RECORDS

	OPMENT				FUNCTI					10507	A' B L R		
	SION DET		/	OR.	OT NO	. FO	7 912	42	64	PROCEDU			
	-74-		28 - 74		70		. RI	509		11 47	(p.54)	NT NUM	t t ters
SPEC	THE RESERVE AND PERSONS NAMED IN				TEST						TEST RE	SULTS	
NO.	B/W (OHM)	TEST CONFIG.	CAP.	CAP VOLT (VOL			TEST GAP (IN)	BOOS CLOS TYPE		FUNC. (YES/NO	FUNC. TIME.	DENT (IN)	OPEN B/W (YES/N
561	4,63	A	22	30.	0					No	-		YES
562	4.73	A .	22	30.	. 0					YES	0.6		YES
563	4.61	_A_	22	30.	.0					No			YES
564	4.65	A	22	30.	0					No			465
565	3.43	A	22	30.	0					YES	0.6		Y55
566	2.85	А	22	30.	.0					YES	0.6		YES
561	2.7/	A	22	30.	0					YES	0.5		YEZ
568	3.71	A	12	30	.0					YES	0,6	an d	YES
569	3.45	_A_	22	30.	0					yes	0.7		YES
510	3.09	Α	22	30.	0					YES	0.6		YES
571	3.24	A	22	40.	.0					YES	0.5		YES
572	2.95	A	22	40	.0			-	200	YES	0.4		YES
<i>573</i>	3.21	A	22	40	.0					YES	0.5		YES
574	3.29	A	22	40	.0					YET	0.5		Yes
	2.92	А	22	40	.0					YES	0.5		YES

- (1) Test Configurations --
 - A Header Assembly Function Time Test (Figure B-1)
 B Header Assembly "No-fire" Test (Figure B-1)

 - C Detonator Dent Output Test (Figure B-2)
 - D Detonator Gap Test (Figure B-3)
 - E Booster (Variable Closure) Initiation Test
 - F "Steel Barrier" Test (Figure B-4)

TABLE C-3
TEST DATA RECORDS

DEVEL	OF TEST					" SENSI		/	10507				
PRECI	SION DE	NIATURE TONATOR	HDI ASS	SY.	OT NO.	FOT %	4:	264	PROCEDU				
TEST	5 - 74		COMPI 28-74		70%	- 1	50		1151	F WITH THE	91 404	BERS	
	IMEN				TEST	1		100.00	I	TEST RE	SULTS		
NO.	B/W (OHM)	TEST CONFIG.	CAP.	CAP. VOLT. (VOLT		TEST GAP (IN)		THICK.	FUNC.	FUNC. TIME.	DENT (IN)	OPEN B/W (YES/N	
576	2.48	Α	22	40.0					YES	0.4	111	YES	
517	3.27	Α	22	40.0	ļ				YES	0.5		YES	
578	2.84	A	22	40.0					YES	0.6		YES	
579	2.91	Α	22	40.0					Y65	0,5	٩	YES "	
580	2.93	A	22	40.0					YEZ	0.6		YES	
581	2.51	Α	22	40.0				log	763	0.5		YES	
582	2.79	A	22	40.0					YEZ	0.5		765	
583	2.77	A	22	40.0					YEZ	Q.4		YES	
584	2.57	A	22	40.0					YET	0.5		YES	
585	2.57	A	22	40.0				يوفيا	YES	0.5	W. H.	YES	
586	2.86	_A_	22	40.0		_	ļ		YES	05		YES	
<u>587</u>	2.52	Α	22	40.0	,			1	YES	0.3		YES	
588	2.51	A	2.2	40.0					YET	04		YES	
589	2.72	A	22	40.0				10.1	YES	0.4		YES	
590	2.67	Α	22	40.0				1 60	YES	0.4	124	YES	

- (1) Test Configurations --
 - A Header Assembly Function Time Test (Figure B-1)
 - B Header Assembly "No-fire" Test (Figure B-1)
 - C Detonator Dent Output Test (Figure B-2)
 - D Detonator Gap Test (Figure B-3)
 - E Booster (Variable Closure) Initiation Test
 - F "Steel Barrier" Test (Figure B-4)

TABLE C-3
TEST DATA RECORDS

	OPMENT				CTION 7				10507					
		NIATURE TONATOR	HD!			T 1	. 14.	.64	1340110	HS 9 51	មើតគ គ	A FIA		
	3-74	1	28-74		700F	17. 13.1	50	%	- 1	1 2 110000	to the Paris to	ittien i		
SPEC	THEN				TEST		1 1000	A.S		TEST RE	sin is			
NO.	B/W (OHM)	TEST CONFIG.	_	CAP. VOLT. (VOLT)	NO- FIRE (AMP)	TEST GAP (IN)	BOOS CLOS TYPE		FUNC.	FUNC. TIME (USEC)	DENT (IN)	OE IN		
591	3.24.	A	22	40.0					YES	0.5		YES		
592	3.51	A	22	40.0					YES	0.4		YES		
593	3.52	A	22	40.0					YES	0.4		YET		
594	3.10	А	22	40.0					YES	0.4		Yes		
595	2.88	A	:22	40.0					YES	0.5		YES		
596	2.93	A	22	40.0					YES	0.5		YES		
597	3.04	A	22	40.0					YES	0.4		YES		
598	3.20	A	22	40.0					YES	0.4		YES		
599	2.93	4	22	40.0					15	0.5		YES		
600	3.29	A	147	30.0					YES	0.4		YES		
601	2.74	A	147	30.0					YES	0,5	36.1	YES		
602	4.56	A	147	30.0					No	_		YES		
603	3.04	A	147	30.0					YES	0.6	L) II i	YES		
604	4.42	4	147	30.0					YES	0.5		Y'57		
605	2.82	A	147	30.0					YES	0.4		YES		

NOTES: (1) Test Configurations --

A - Header Assembly Function Time Test (Figure B-1)

B - Header Assembly "No-fire" Test (Figure B-1)

C - Detonator Dent Output Test (Figure B-2)

D - Detonator Gap Test (Figure B-3)

E - Booster (Variable Closure) Initiation Test

(Figure B-3)

TABLE C-3 TEST DATA RECORDS

	OPMENT			PAR/	NCTION '	SENSIT	IVITY/		10507	MAER			
PRECI	SION DE	TONATOR	/ A:	DR. LOI		LOT ~I.	1 1 10	64		JRE NUM	A R A IE	ARA, S	
	3-74		COMPL.		700F		500	1011	TEST FOR PARALLARIT				
	IMEN				TEST				TEST RE	SULTS			
NO.	B/W (OHM)	TEST CONFIG.	CAP.	CAP. VOLT. (VOLT)		TEST GAP (IN)	BOOS CLOS TYPE		FUNC.	FUNC. TIME (USEC)	DENT (IN)	OPEN B/W (YES/)	
606	2.82	A	147	30.0					YES	0.4		YES	
607	2.76	A	147	30.0					Yes	0.4		YES	
608	2.79	Α	147	30.0					YES	0.4		YES	
609	2.98	A	147	30.0	~	D TO READ IN	~		YES	0.5		YES	
610	2.91	A	147	30.0					YES	0,5		YES	
611	3.24	A	147	20.0					Yes	0,5		YO	
612	2.87	_A_	147	30.0		me			YES	0.5		YES	
613	3.46	Α	147	30.0		-11			YES	0.4		YES	
614	-2.85	A	147	30.0					YES	0.4		YES	
615	3.01	A	22	40.0					YES	0.4		YES	
616	2.66	- A	22	40.0					YES	0.4		YES	
617	2:95	A	22	40.0					YES	0.5		YES	
618	2.77	A	22	40.0					Y65	0.5		YES	
619	3.47	A -	22	40.0		. =			YES	0.4		YES	
620	2.74	A	22	40.0					YE'S	0.4		YES	

NOTES: (1) Test Configurations --

A - Header Assembly Function Time Test (Figure B-1)
B - Header Assembly "No-fire" Test (Figure B-1)
C - Detonator Dent Output Test (Figure B-2)

D - Detonator Gap Test (Figure B-3) E - Booster (Variable Closure) Initiation Test (Figure B-3)

TABLE C-3
TEST DATA RECORDS

DEVEL	OPMENT				FUNCTION	MIT P	:/ou	TPUT		10507				
PRECI	SION DE	NIATURE	HD AS	R. SY.	OT NO,	1.07	15 1 21		64	PROCEDU	RE NUME	BER & P	ARA, NO	
TEST:	START	TEST	COMPL	FTE	AMH. F	MP.	4	L. H.)	IIDII	1141	31-41-61	NE NOM	1) 1 +/	
5-3	-74	5-	28-74	-	7001	_		50%	6					
SPEC	IMEN				TEST			7000	60 m m		TEST RE	TEST RESULTS		
NO.	B/W (OHM)	TEST CONFIG.	CAP.	VOLT (VOL		· GA	ST P N)	BOOS CLOS TYPE	THICK.	FINC	FUNC. TIME (USEC)	DENT (IN)	OPEN B/W (YES/N	
621	2.71	A	22	40.	0					YES	0.4		Y65	
622	2.90	A	22	40.	0					46'5	0.5		YES	
				}										

NOTES: (1) Test Configurations --

A - Header Assembly Function Time Test (Figure B-1)

B - Header Assembly "No-fire" Test (Figure B-1)

C - Detonator Dent Output Test (Figure B-2)

D - Detonator Gap Test (Figure B-3)

E - Booster (Variable Closure) Initiation Test

(Figure B-3)

TABLE C-3 TEST DATA RECORDS

	OPMENT				AHAMETER			/	10507				
PART	SION DE				OF NO.	UT 51.	I CR	264	PROCEDURE NUMBER & PARA, NO				
TEST :		1	COMPL		AMB, TEM	P. RE	L, HU	TEST EQUIPMENT NUMBERS					
5-1	3-74	5-2	28-7-	4	7/0F TEST		50°		TEST RE	CIN TC			
SPEC	IMEN	TEST (1)		CAP		TEST	BOOS			SPECI	MEN		
NO.	B/W (OHM)	CONFIG.	CAP. (UFD)	VOLT (VOL	FIRE	GAP (IN)	TYPE	THICK.	FUNC. (YES/NO	EUNC. TIME (USEC)	DENT (IN)	OPEN B/W (YES/N	
651	4.28	В			0.150				YES			YES	
652	3.34	B			0.145				YES			YES	
653	4.12	В			0.140				No			YES	
654	4.52	В			0.145				YES			YEZ	
655	3.02	В		***************************************	0.140				No			YES	
656	3.23	3			0.145				YES			Atz	
657	2.97	B			0.140				No			YES	
658	2.89	B			0.145	* p spinish spinora-coli			No			YES	
659	3.33	В			0.150				YES			YES	
660	3.00	В			0.145				No			YES	
661	3.44	B			0.150				YES			YES	
662	3.35	B			0.145				YES			YEZ	
663	3.13	3			0.140				YES	•		YES	
664	3.20	В			0.135				YES			YES	
665	3.54	B			0.130				YES			YES	

- (1) Test Configurations --
 - A Header Assembly Function Time Test (Figure B-1)
 B Header Assembly "No-fire" Test (Figure B-1)

 - C Detonator Dent Output Test (Figure B-2)
 - D Detonator Gap Test (Figure B-3)
 - E Booster (Variable Closure) Initiation Test (Figure B-3)
 - F "Steel Barrier" Test (Figure B-4)

TABLE C-3
TEST DATA RECORDS

	OPMENT				INCTION 3			1	10507					
PRECI	SION DE	NIATURE TONATOR	/ AS	OR. LO	T NO.	LOT 51.	7 E C 6/1	264	PROCEDURE NUMBER & PARA, NO					
	START		28-74		Mac. 10 11 11 1					IFST FOURMENT NUMBERS				
SPEC	3-74	3 - 4	28-14	-	710F TEST		50		Tirem Do	CIN TIC				
		TEST (1)		CAP.	NO-	TEST	B009			TEST RE	MEN			
NO.	B/W (OHM)	CONFIG.	CAP.	VOLT. (VOLT)	FIRE (AMP)	GAP (IN)	TYPE	THICK.	FUNC. (YES/NO	FUNC.	DENT (IN)	OPEN B/W (YES/N		
666	3.98	B			0.125				No			YES		
667	3.93	B			0.130				YES			YES		
668	4.24	B			0.125				Yes			YES		
669	3.56	B			0,120				YES			YES		
670	3.19	B			0.115				No			YES		
671	3.20	В			0.120				No			1/65		
672	3.49	B			0.125				YEZ			YES		
673	3.12	В			0.120				No			YES		
674	3.21	B			0.125				No			YES		
675	3.33	B			0.130		111-		YES			YET		
676	3.74	B			0.125				YES			YES		
677	4.30	B			0.120				Y55			YES		
678	2.73	B			0.115				No			YES		
679	4.10	В			0,120				YES			YES		
680	4.37	B			0.115				455			YES		

- (1) Test Configurations --
 - A Header Assembly Function Time Test (Figure B-1)
 - B Header Assembly "No-fire" Test (Figure B-1)
 - C Detonator Dent Output Test (Figure B-2)
 - D Detonator Gap Test (Figure B-3)
 - E Booster (Variable Closure) Initiation Test (Figure B-3)
 - F "Steel Barrier" Test (Figure B-4)

	LOPPENT			FL	NOTTO	" SENSI	TIVITY	1	fAII *.	.'H1 H	200	- I van gemeente de		
PREC	NAME MI ISION DE	TOUSTOR		1	T NO.	0 1 51	26 - 179	264	PROCEDURE S NEER & FARA					
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SPE	CIMEN				TEST					List desums				
NO.	B/W	THST (1)	CAP.	CAP.		TEST		STER SURE	FUNC.2)	I wind will		30033		
	(OHM)	CONFIG.	(UFD)	(VOLT)		(IN)	TYPE	THICK.	(YES/NO	III a	DENT (IN)	FUNC.		
1	NOZE 2,3	C				0.250			YES		0.020			
2	1	C.				0.150			YES		0.013			
3		D				0.250	AL	.005	YES			YES		
4		D				0.250	AL	.005	YES			YES		
5		D				0.250	AL	.005	YES			YES		
6		D				0.250	AL	.005	YES			12.5		
7		D				0.250	AL	.005	yE5			YES		
8		c				0.500			YES		0.020			
9		D		******************************		0.500	AL	.005	YES			YES		
10		D				0,500	AL	.005	YES			No		
11		D				0.500	AL	,005	YES			YES		
12		D				0.500	AL	.005	YE5			No		
13		D				0.500	AL	.005	YES			YES		
14	Note 213	D				0.500	ML	.005	YES			YES		

NOTES: (1) Test Configurations --

A - Header Assembly Function Time Test (Figure B-1)

B - Header Assembly "No-fire" Test (Figure B-1)

C - Detonator Dent Output Test (Figure B-2)

D - Detonator Gap Test (Figure B-3)

E - Booster (Variable Closure) Initiation Test (Figure B-3)

- (2) Det functioned with M100 match (no header)
- (3) Can Base was flat

TABLE C-3
TEST DATA RECORDS

	OPMENT					SENSIT			1 7 3					
	SION DE				4264					ENULLIDORE OF THE A FALA				
1	11-74	11 11 11 11	12-7	1	7201		52	%	,	٠ ، ، .		7/		
	HNEN				TEST		1 1500	2017	FEVT TO THE PER PER PER PER PER PER PER PER PER PE					
NO.	B/W (OIM)	TEST CONFIG.	0.11 .	CAP. VOLT. (VOLT		TEST GAP (IN)	BOOS CLOS TYPE		FINC(2)		DENT (IN)	BNOST: FUNC. (YEG U		
1	Note 2,3	D				0.250	AL	.005	YES			No		
2	1	D				0.150	AL	.005	YES		v. 030	No		
3		C				0.150			YES		0.041			
4		D				0.125	AL	.005	YES			YES		
5		D				0.125	AL	.005	YES			YES		
6		D				0.125	AL	.005	YES			YES		
7		D				0.125	AL	.005	YES			No		
8		D				0,125	AL	,005	YES			YES		
9		D				0.125	AL	.005	YES			YES		
10		D				0.125	AL	.005	YES			YES		
11		D				0.125	AL	.005	YES			YES		
12		D				0.125	AL	.005	YES			YES		
13	NOTE 2, 3	1				0.125	AL	.005	YES			YES		
									1111					

NOTES: (1) Test Configurations --

A - Header Assembly Function Time Test (Figure B-1)

B - Header Assembly "No-fire" Test (Figure B-1)

C - Detonator Dent Output Test (Figure B-2)

D - Detonator Gap Test (Figure B-3)

E - Booster (Variable Closure) Initiation Test

(Figure B-3)

F - "Steel Barrier" Test (Figure B-4)

(2) Det functioned with M100 match (no header)

(3) Can base was flat

APPENDIX D

RADC RELIABILITY EVALUATION OF MUNITION DEPOSITED FUZE HEADER SAMPLES (P/N 08892)

Headquarters Armament Development and Test Center (AFSC), Eglin AFB, Florida, requested RADC reliability support involving evaluation of munition fuze headers on 27 February 1974. Attachment #1 is the formal correspondence from Headquarters ADTC/SDH requesting RADC support and containing device performance requirements, reliability problems of immediate concern and a tentative analysis plan. The analysis plan defined two categories, namely header material analysis and reliability stress tests. RADC/RBRP received nine (9) munition fuze headers for reliability assessment. RADC's evaluation of header materials and manufacturing processes indicated an inferior product from the reliability standpoint, thus the test program suggested was considered not warranted at this time. RADC analysis results documented herein respond to items 3b, c, d and e of referenced attachment #1. Mr. Origer ADTC/SDHZ stated by telecon on 14 March 74 that subject fuze headers were prototype samples for evaluation rather than actual devices currently incorporated in munition fuze designs. This report documents the fuze header analysis findings as conducted by the RADC QR Failure Analysis Activity. RADC/RBRP personnel assigned to this project were Messrs. J. J. Bart, C. J. Salvo and G. G. Sweet. RADC/RBRM personnel were Messrs. C. Lane and B. Moore.

Fuze Header Reliability Analysis Results:

photo of the header surface with deposited film geometry highlighted. Figure 1C SEM photos verify that the deposited two layer thin film was evaporated over the center conductor material. From this we also conclude that the film is smooth when compared with the plating on the inner and outer conductors. The film itself if designed as a fuzable link between two terminal conductors which is blown by energy from a capacitor discharge circuit. Lead Azide, Pb(N₃)₂, material is positioned over the fuze link and explodes when the film temperature reaches 350°C. Since lead azide is a needle-like crystal, it is assumed that these crystals are held in place with a binder (possibly dextrin-adhesive substance) when positioned over the film fuze link. The results of Electron Beam Microprobe X-Ray analysis identified the header materials and are listed below:

Thin film fuze material - vapor deposited two layer film of palladium (Pd) and silver (Ag). Optical and SEM analysis indicates that the Pd is deposited on the glass and conductor surfaces first followed by deposition of Ag.

Conductor materials - Both the center and outer rim portion of the header conductors are an iron-nickel-cobalt (Fe, Ni, Co) Kovar

material which has been plated with a gold (Au)-Tantalum (Ta) material. The color of this plating (silver-gray) indicates the simultaneous plating of both materials. The Au and Ta volume percentages were not determined.

Glass dielectric material - This insulator appears to be a low melting point glass containing: Sodium (Na), Potassium (K), Aluminum (Al), Silicon (Si) and Oxygen (O). Thus, the header construction implies a Kovar to glass seal, an established, reliable technology used throughout the microelectronics industry for package fabrication, however, the glass is not high purity.

The X-Ray spectral readouts for the above designated materials are shown in Figure 1D. Figure 2 shows the fuze link neckdown region and associated film profilometer trace where the measured total thickness was $6000~\text{A}^{\circ}$. The nominal resistance of the film as measured on all samples was 304 ohms. Figures 3 and 4 show two typical fuze headers with corresponding profilometer traces of the surface structure revealing step heights, general surface planarity variations and relative roughness of the materials. Figure 4B shows a SEM photomicrograph of an edge of the thin film fuze link pattern delineating the two layer deposition of Pd and Ag. Pd is deposited on the glass first because of its adherence properties, followed by Ag deposition. The Pd and Ag thicknesses could not be measured due to the geometrical properties of the profilometer stylus. It appears that two successive depositions, Pd then Ag, were made followed by film definition using photomasks and selective chemical etch of metals simultaneously. The exposed narrow width of Pd observed could be the result of inadequate etching time. Only one (1) of the nine (9) units exhibited this characteristic.

General Conclusions and Related Discussion:

(a) Materials Compatibility:

It appears that the selection of Ta-Au and Pd-Ag for conductor plating and fuze link respectively was based on the fact that these metals do not react with Pb(N₃)₂, lead azide, and as such represent a chemically inert material system. Although lead azide is not hygroscopic, it will react with water forming a compound (weak acid) which is also chemically inert with the fuze materials. Lead azide requires special handling for shipping and storage in that water submersion is necessary to reduce sensitivity. The use of the noble metals Au and Ag results in the absence of corrosion or oxidation problems. One potential reliability problem with the plating is porosity of the Ta-Au plate over Kovar. Kovar (Fe-Ni-Co) will rust in the presence of moisture and thus the porosity of the plating is

critical. Inspection of the fuze header plating indicates a poor quality plate with large pits and general surface roughness. If one also considers the intermetallics formed by the Ta-Au plate with the Pd-Ag film during deposition, it is a possibility that some degree of Kirkendall voiding will occur. The Kirkendall effect occurs in diffusion couples and involves mass transfer of one constituent due to a more rapid diffusion rate with resultant void formation on the side of the couple containing the faster-diffusing constituent. The severity of this voiding depends on temperature and time during deposition and the degree of voiding necessary to create a reliability problem (metal opens) depends on the film thickness and contact area and/or periphery. A more obvious condition which exists in these devices in the non-planarity of the glass between the center and outer cylindrical conductors. If a valley, due to glass dewetting, exists at the glass-center conductor interface, inadequate rilm coverage may occur during deposition leading to an open. In addition, the measured plating thickness to film thickness ratio (~6:1) is excessive again resulting in reduced coverage at the step and notential film opens.

(b) Manufacturing Process Fvaluation:

Several characteristics of the fuze header structure are considered poor design from the reliability standpoint. The porosity of the Ta-Au plate can lead to rust in the presence of moisture. The excess step (~3.60 μ) over which the ~0.60 μ Pd-Ag film is deposited could result in metal opens. The glass non-planarity may result in poor deposition and varying film thickness, especially at the narrow fuze link region, depending on the evaporation source configuration. It seems like polishing the glass to reasonable planarity prior to plating and thin film deposition would result in a more reliable product. Reducing the plate thickness and porosity would result in better step coverage of the thin film Pd-Ag over the plated conductors. The use of a high purity glass is commensurate with the 20 year storage requirement, yet a glass containing relatively high percentages of contaminants was used which exhibited voids (gas pockets) and general surface roughness. The thin film metal pattern positioning (centering) indicates a lack of process control in metal definition. Since maximum contact periphery minimizes the probability of metal film opens (thinning at steps), a critical requirement when coverage over large steps is involved as is the case here, a more reliable thin film design geometry would consist of complete overlap of the plated center conductor. This would result in maximum contact area and periphery at the center conductor to glass step. The manufacturers' current design obviously is not designed for contact reliability and improper film centering significantly reduces contact periphery.

(c) Environmental Screen Tests:

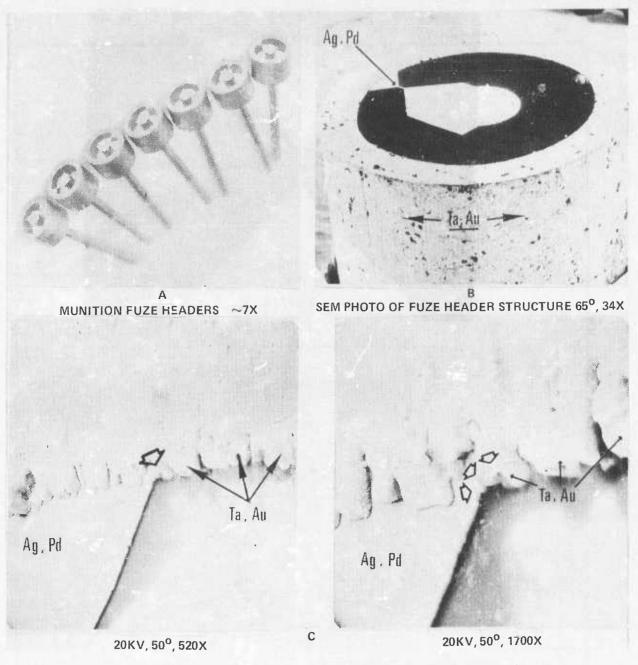
Based on the excessive center conductor step height to film thickness ratio ($\sim 6:1$) we conclude that the most applicable environmental screen test to effectively remove potential fuze header metal open failures is thermal shock and/or temperature cycling with post electrical continuity tests.

RADC Recommended Fuze Header Disposition:

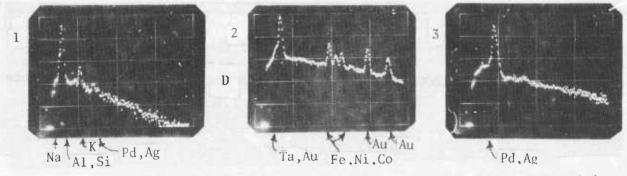
Based on the analysis findings, RADC considers these fuze headers not suitable for high-reliability applications. It was therefore decided that extensive environmental and thermal stress testing was not warranted at this time.

Edgar a. Doyle Jr. EDGAR A. DOYLE, JR.

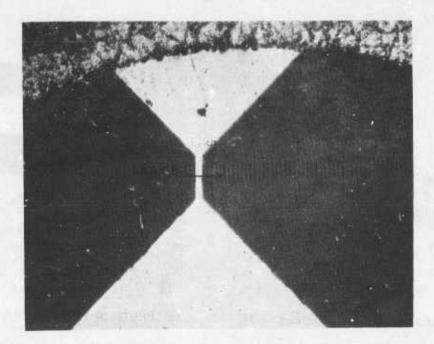
Reliability Physics Section Reliability Branch RADC



SEM Photos Verifying Pd, Ag Double Layer Thin Film Deposited Over Ta-Au Plated Kovar



Electron Beam Microprobe Readouts (X-Ray Spectrum) of (1) Glass Composition, (2) Center Conductor Plate and Base Material and (3) Thin Film Composition Figure 1.



200X Scale = $6.25 \mu m/Div$

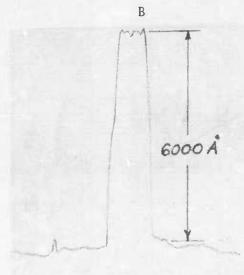
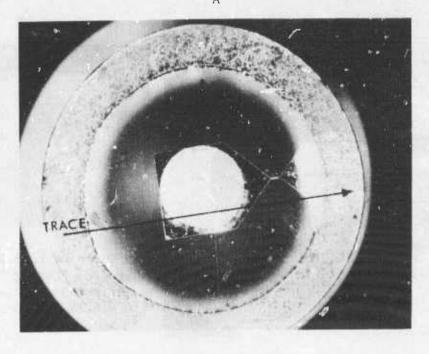


Figure 2. Photomicrograph and Profilometer Trace Showing
Film Thickness of Fuze Link
Profilometer - 1000X Horizontal, 10K Angstroms Full Scale Vertical. Fuze #1



50X Darkfield

F

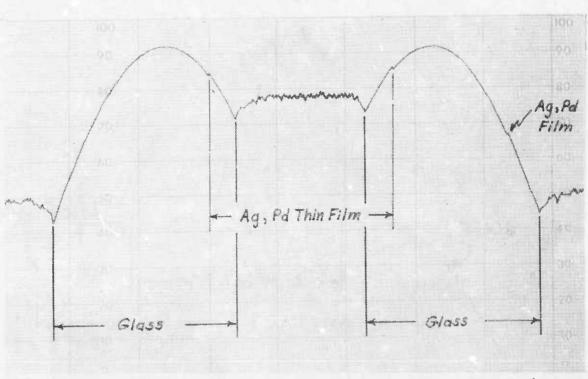
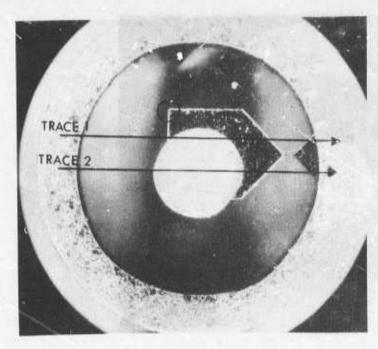
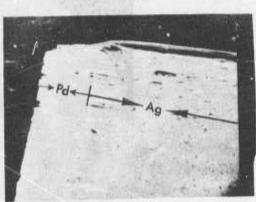


Figure 3. Photomicrograph and Profilometer Trace of Fuze Header Profilometer - 100X Horizontal, 500K Angstroms Full Scale Vertical. Fuze #2





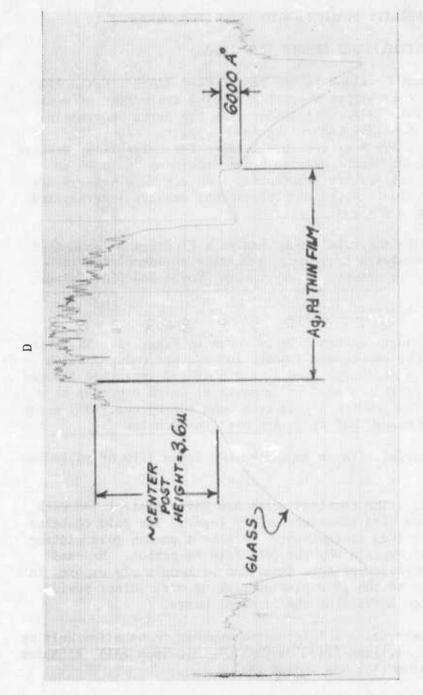
SEM Photo of Fuze Region (Circled) Showing Double Layer Metal Structure 1200X 5 KV 30°.

50X Darkfield

My GLASS 6000 A My

C

Figure 4. Photomicrograph and Profilometer Trace of Fuze Header Profilometer - 100X Horizontal, 100K Angstroms Full Scale Vertical. Fuze #4



Trace 2

Figure 4 (Concluded). Profilometer Trace 2 100X Horizontal, 100K Angstroms Full Scale Vertical. Fuze #4

APPENDIX E

RADC RELIABILITY EVALUATION OF DEPOSITED BRIDGE

MUNITION FUZE HEADER (P/N 10506)

Headquarters Armament Development and Test Center (AFSC), Eglin AFB Florida, requested RADC reliability support involving evaluation of munition fuze headers on 6 June 1974. Attachment 1 is the formal correspondence from Headquarters ADTC/SDY requesting RADC support. RADC/RBRP received thirty (30) PN 10506 munition fuze headers for reliability assessment. RADC's evaluation of header materials and processes indicate an inferior product from a reliability standpoint. Subject fuze headers are prototype samples for evaluation, rather than actual devices incorporated into current munition fuze designs.

This report documents the fuze header analysis findings as conducted by the RADC QR Failure Analysis Activity. RADC/RBRP personnel contributing to this project were Messrs. JJ. Bart, E.A. Doyle and D.J. Salvo.

Fuze Header Reliability Analysis Results:

The overall fuze header construction is shown in Figure 1. The thin film conductor between the two terminal posts forms a hot bridge, which is heated by a capacitive discharge from a 22 microfarad capacitor charged to 40 volts. The heat ignites a lead azide material which explodes at a temperature of 350°C. The results of electron beam microprobe (EBM) x-ray analysis identified the header materials and are listed below:

Thin form fuze material - Vapor deposited two layer film of palladium (Pd) and silver (Ag).

Conductor materials - The terminal posts are Kovar post-plated with gold (Au) over a chromium (Cr) adhesion-barrier layer. The gold contains a large amount of copper (Cu) contaminant. This is a common gold plating bath contaminant and may explain why the gold film is porous. Exposed Kovar exhibited rust corrosion on some fuzes and is completely exposed in spots on other fuzes due to the gold plating flaking off. Glass residue was also found on the top surface of the terminal posts.

Glass dielectric material - The insulator appears to be a low melting point glass containing: silicon (Si), oxygen (O), aluminum (Al), titanium (Ti), iron (Fe), potassium (K), and sodium (Na).

Electrical resistance measured 4.09 ohms average on 17 samples tested and varied from a minimum of 3.50 ohms to a maximum of 5.25 ohms. Profilometer trace normal to the neckdown region of the thin film measured a nominal film thickness of approximately 4,000 Angstroms. Profilometer traces from terminal post to terminal post indicate step heights, relative

roughness of materials, and general surface planarity variations. Step heights at the posts were as large as 70,000 Angstroms. Examples of typical profilometer traces are given in Figures 2 and 3. Optical and scanning electron beam microscope (SEM) photomicrographs show a variety of features found in several devices. Included are examples of thin film misalignment, gold flaking, rusting, bubbles in the glass, surface testure of plating on terminal posts, plating pop-outs, and glass defects in the thin film fuze region.

General Conclusions and Related Discussion:

a. Material Compatibility

Reference is made to RADC's report on fuze headers P/N 08892 dated April 74, for detailed discussion of materials compatibility. The comments apply in general, although the plating of the terminal posts and outside cylinder are Au-Cr, rather than Au-Ta used in P/N 08892.

b. Manufacturing Process Evaluation

In summary, the following process deficiences are noted in the subject (P/N 10506) fuze headers: (1) Poor plating over Kovar: a) Corrosion (rust) is evident on several samples indicating porosity incompatible with long term reliability; b) Flaking off of plating materials indicating poor adherence possibly caused by improper Kovar surface pre-Present Au post-plating minimum thickness spec for microcircuit packages (Kovar leads) is 50μ -in (1.25μ) . Tests have shown that a continuous Au plate requires a minimum thickness of 25 - $35\mu\text{-in}$. Thus, a $50\mu\text{-in}$ Au plating thickness is adequate provided the complete removal of the metal oxide, which is grown to facilitate glass to metal hermetic seals, does not roughen the surface of Kovar itself and plating is initiated immediately after oxide removal, that is, before the formation of native oxide from atmospheric exposure. This assures a relatively smooth metal plate with fair adherence properties. A thin Cr or Ti layer may be used prior to Au plating for better adherence observing the same precautions. Assuming a nominal 5000Å (0.5μ) total film thickness, the step height maximum ratio of 2:1 (12,500Å:5,000Å) is nearly achieved reducing the risk of opens at the post step. (2) Lack of glass insulator planarity leading to possible thin regions in the vapor deposited thin films during the deposition process. (3) Possibility of open circuit or premature burnout at lower than 350°C due to a) excessive step height to film thickness ratio, (terminal post to thin film fuze link); (ratio should not exceed 2:1); b) bubbles in the glass in the fuze region; c) small contact periphery afforded by the two terminal post electrode geometry; d) glass contamination on the posts. (4) Process control problem indicated by off centered thin film deposition and by fuze bottom thin film (Pd) deposition extending beyond top thin film (Ag) deposition on several devices. (5) Glass insulator containing many impurities which are possible long term sources of corrosion and/or

thin film contamination. Reference report on fuze P/N 08892 for further discussion of similar deficiences noted on that part.

c. Recommendations

RADC recommends that these headers not be considered for high reliability (20 year storage) applications. The problems noted on this part are more severe from a design and process standpoint than those noted in the RADC report on P/N 08892 fuze headers.

The basic concept of using a plated fuze link seems to have some merit. After giving careful consideration to the fuze header designs submitted for evaluation, the following design and process changes are suggested to possibly enhance reliability, refer to Figure 9a. The top view shows a split cylinder arrangement which allows the thin film fuze link to have maximum contact periphery over the glass to metal step. Alignment of the thin film is also less critical since the electrode contact is the entire half cylinder rather than a small post. A possible process sequence would be to start with a metal cylinder having a bottom but no top. Fill the interior of the cylinder with a high purity bubble free glass. Mechanically polish the top surface to achieve a smooth, planar surface with no step at the glass to metal interface. Use a laser, diamond blade, or air-abrasive to cut the metal cylinder in two. Cut down one side, across the bottom between the pins, and up the other side. (Alternately, one could start with two half cylinders and devise fixturing to keep the glass in place while it is molten). Apply a protective plating on the cylinder and pins assuring that the plating is fine grained having low porosity yet minimum thickness to assure that the step height from metal to glass does not exceed two (2) times the thickness of the thin film plating. Deposit the thin film fuze link by vapor deposition method and delineate by etching or masking during the plating process. Appropriate cleaning and surface preparation steps are assumed. Since the glass to metal seal does not have to hold a vacuum, it may be possible to use some other metal-insulator system in place of Kovar. This might permit dispensing with the plating operation required with the Kovar. Attachment 2 is extracted from "Handbook of Materials and Techniques for Vacuum Devices", Walter H. Kohl, Reinhold Publishing Corp., N.Y., 1967 and contains data on various glass-metal sealing systems.

Consideration should also be given to a system using a ceramic insulator in place of the glass, although no data on ceramic-metal seals is available at RBRP to determine compatibility.

One such configuration, similar to the P/N 10506 design, involves a ceramic (Al $_2$ O $_3$) disc with swaged Au alloy terminals and thick film Au or Au alloy as the fuze link. The terminal lead cross-section can be any geometry other than circular to avoid lead rotation (See Figure 9b).

Another possible alternative is to adapt commercially available hybrid resistor chips to the fuze application. This would entail attachment of contact pins to the resistors, special trimming of the resistor element to insure a hot spot (normally designed out in normal resistor applications), and a determination of compatibility of the resistor materials with the lead azide environment and 350°C hot bridge temperature. This technology is very mature and a wide variety of substrates, contact pad materials, and resistive materials are available. Trimming to very precise values of resistance is achieved by a wide variety of methods and a consistent product is readily obtainable. Attached is descriptive literature of one manufacturer's thick film hybrid resistors (Attachment 3). Thin film resistors are also available in similar configuration. Lead attachment (contact pins) would appear to be the most difficult problem to be solved. Conventional flywire or reflow solder attachment do not appear compatible with this fuze application.

CARMINE J. SALVO

Reliability Physics Section

Reliability Branch

Carmine Halvo

Edgar a. Doyle Jr. EDGAR A. DOYLE, JR.

Reliability Physics Section

Reliability Branch

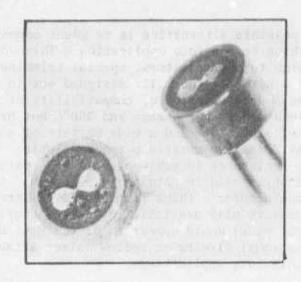


Figure 1. Fuze Overall Construction (Approx 13X)

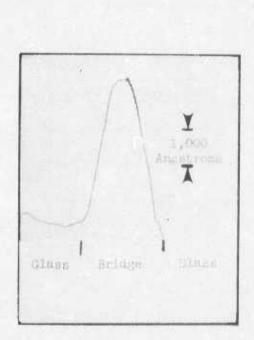


Figure 2. Profilometer Trace Normal to Neckdown Region of Fuze Thin Film. 1,000X Horiz.

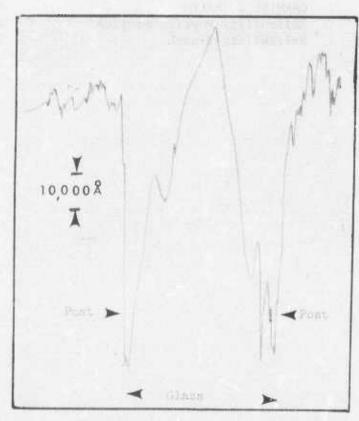


Figure 3. Profilometer Trace From Post to Post Showing Post Roughness, Metal-Glass Step, and Lack of Planarity of Glass in Fuze Link Region. 100,000 Angstroms Full Scale, 100X Horiz.

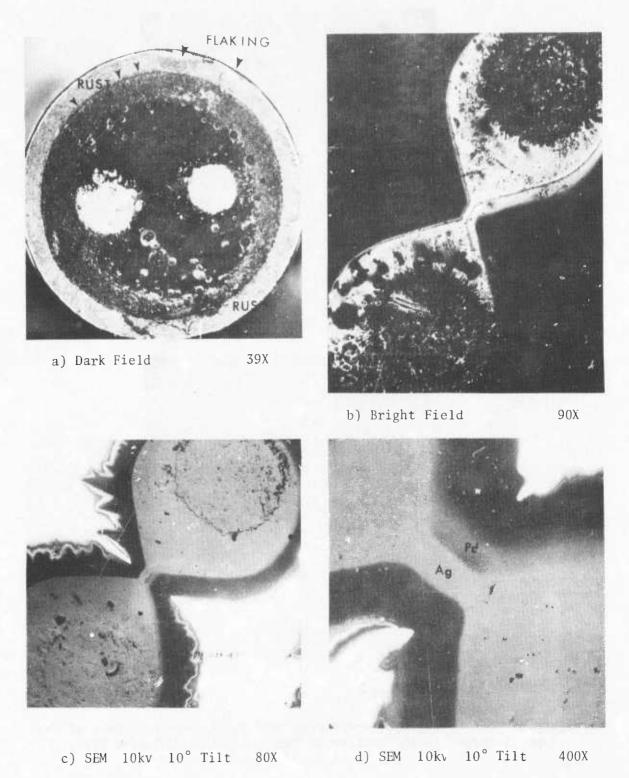


Figure 4. Fuze #1 a) Bubbles in glass; gold flaking; rusting; off centered thin film; b) Bottom layer of thin fi'm extending beyond top layer; c) Holes in thin film and bottom layer extension; d) Bottom layer extending beyond top.

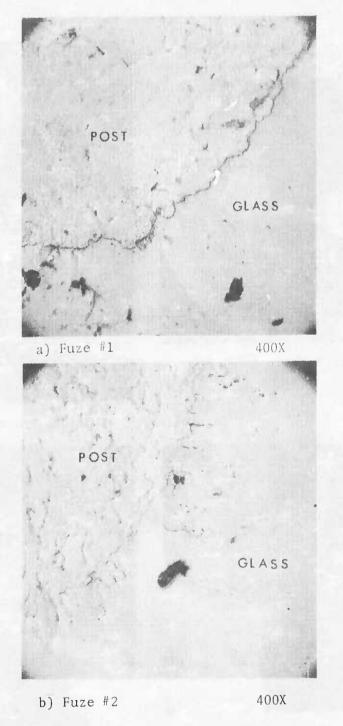
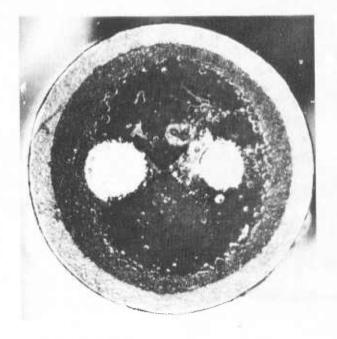
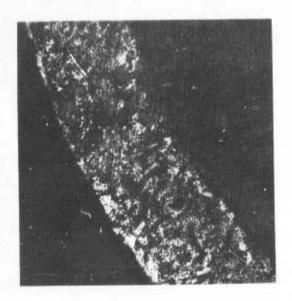


Figure 5. SEM Photographs Indicating Surface at Terminal Posts of Two Typcial Fuzes (Both Photographs Taken at 10kv, 10 Degree Tilt)

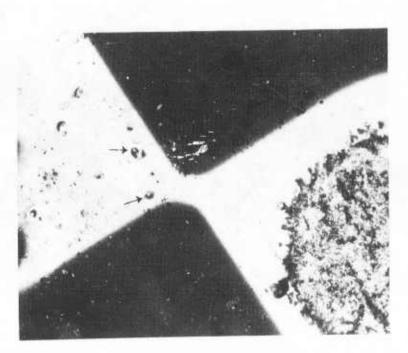




a) Dark Field

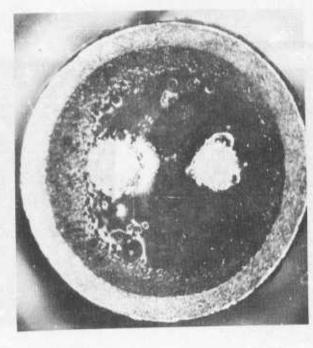
39X

b) Bright Field



c) Bright Field

Figure 6. Fuze #7 a) Bubbles in Glass; gold flaking; rusting; b) Flaked Region of Outside Cylinder; c) Glass Defects in Fuze Thin Film Region



a) Dark Field



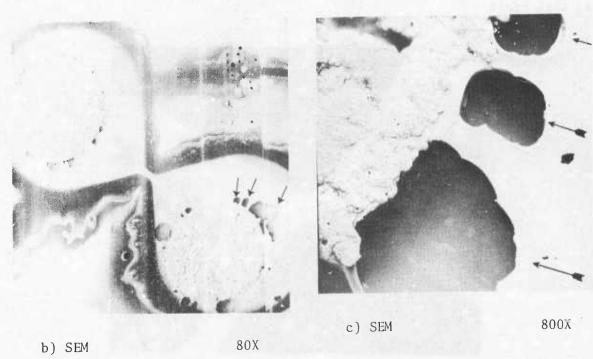
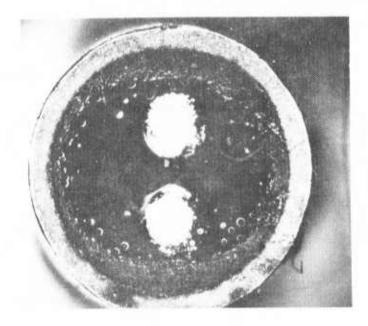
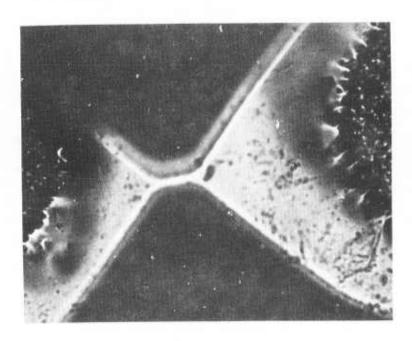


Figure 7. Fuze #8 a) Bubbles in glass; rusting; b)&c) SEM showing plating popouts of the thin film around the posts apparently due to bubbles in glass. Note also the texture of post surface in c). SEM taken at 20kv and 10° tilt angle.



a) Dark Field

39X



b) Bright Field

Figure 8. Fuze #9 a) Bubbles in Glass; Rusting; b) Underplating Extending Beyond Overplating; Apparent Thinning of Top Plating in Neck-Down Region; it is possible that the narrowing seen in the top plating is due to etching of the thin film top layer such that the cross-section is triangular.

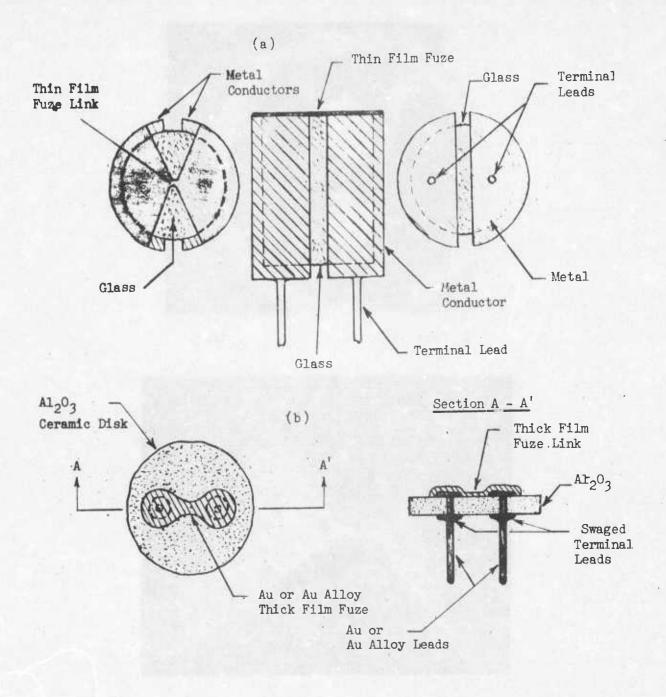


Figure 9. a) Split cylinder fuze header; b) Metal-ceramic disc alternate design

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